

## COLOR SOLID-STATE IMAGE PICKUP DEVICE

### Background of the Invention

#### 1. Field of the Invention

5 The present invention relates to a color solid-state image pickup device.

#### 2. Description of the Related Art

In relation to a CCD (charge-coupled device) 10 semiconductor solid-state image pickup element and a CMOS semiconductor solid-state image pickup element, as described in, e.g., US Patent No. 3971065, which will be described below, color filters having different spectral transmission factors are stacked on a plurality of photodiodes arranged in a 15 two-dimensional array, thereby enabling pickup of a color image.

Two types of color filters are available: namely, red (R), green (G), and blue (B) color filters of a primary color system; and color filters of a complementary color system which permit passage of light of colors complementary to R, G, and 20 B.

In the color filters of primary color system, for instance, a B filter primarily permits passage of only light having a short wavelength of 470 nm or less. Hence, a photodiode of a light-receiving section with the B filter stacked thereon 25 has sensitivity to B incident light. However, the B filter

blocks light having other wavelength components (e.g., G and R), and hence G and R wavelength components that have entered the B filter are not subjected to photoelectric conversion. Thus, color filters of this type suffer a problem of waste of 5 G and R incident light rays and a failure in effective utilization thereof.

In contrast, in the case of the color filters of the complementary color system—spectral filters for permitting passage of light of wavelengths complementary to the primary 10 color components R, G, and B—the color filters are constituted of a yellow (Ye) filter for permitting passage of G and R components complementary to B, a magenta (Mg) filter for permitting passage of B and R components complementary to G, and a cyan (Cy) filter for permitting passage of B and G color 15 components complementary to R. Of the incident light, light wasted by the color filters of complementary color system becomes smaller in quantity than that wasted as a result of use of the color filters of the primary color system. Specifically, the solid-state image pickup device using the complementary color 20 filters can utilize wavelengths of incident light over a wide range and hence has a characteristic of an increase in sensitivity. For this reason, a video movie camera (for photographing a moving image) which encounters difficulty in utilizing an auxiliary light source, such as a flash, frequently 25 adopts a solid-state image pickup device using complementary

color filters.

Meanwhile, in a solid-state image pickup device using color filters of a complementary color system, a signal output from a pixel with a Ye filter stacked thereon becomes a G+R signal; a signal output from a pixel with a Cy filter stacked thereon becomes a G+B signal; and a signal output from a pixel with a Mg filter stacked thereon becomes an R+B signal. Hence, after the G+R, G+B, and R+B signals have been read from the solid-state image pickup device, the signals must be subjected to a color signal separation computation processing performed by an external circuit, thereby extracting R, G, and B signal components.

Specifically, the solid-state image pickup device using the filters of a complementary color system require color signal separation computation processing. Hence, when compared with a solid-state image pickup device using color filters of a primary color system capable of directly obtaining signals of R, G, and B color components, the solid-state image pickup device using the filters of complementary color system suffers a problem of deterioration of image quality in terms of color reproducibility and noise. Therefore, a still camera placing an emphasis on image quality (i.e., a camera for photographing a still image) frequently adopts a solid-state image pickup device using color filters of a primary color system.

Sensitivity is compensated for by means of an auxiliary light

source.

"A Planar Silicon Photosensor with an Optimal Spectral Response for Detecting Printed Material" by Paul A. Gary and John G. Linvill, IEEE TRANSACTIONS ON ELECTRON DEVICES, Vol.

5 ED-15, No. 1, January, 1968. (hereinafter referred to as "Publication 1") describes dependence of a photoelectric conversion characteristic of a photodiode on the depthwise position of a silicon substrate as well as on the wavelength of incident light.

10 An example of solid-state color imager comprised of three photo-sensitive layers, to which this idea has been applied is described in USP No. 4,438,455, which will be provided below.

The solid-state color imager with three photo-sensitive layers of USP No. 4,438,455 configured on the principle described 15 in Publication 1 has a structure for extracting signals of three colors; i.e., R, G, and B. Without using color filters over-laid on the photo-sensitive elements, no light absorption of color filter material has arisen, and hence, incident light can be effectively converted into an electric signal.

20 As shown in Fig. 55 (corresponding to Fig 3 of USP No. 4,438,455), USP No. 4,438,455 describes a structure 101 embodied by means of superimposing three photo-sensitive layers 102, 103, 104 and changing the depth of each photo-conductive layer against the incident light to apply the principle described 25 in Publication 1 to the above structure.

The other example of CCD and MOS type solid-state color imager to which this idea has been applied is described in JP-A-1-134966, which will be provided below.

The solid-state color imager of JP-A-1-134966 configured 5 on the principle described in Publication 1 has a structure of three story  $N^+P$  photo-diode with different depth for extracting signals of three colors; i.e., R, G, and B, from one pixel. Without using color filters over-laid on the photo-diode elements, no light absorption of color filter 10 material has arisen, and hence, incident light can be effectively converted into electric signal. Further, false signals or false colors, such as moiré, can be improved.

As shown in Figs. 56A to 56C (corresponding to Figs. 1(a) to 1(c) of JP-A-1-134966), JP-A-1-134966 describes a structure 15 embodied by means of changing the depth of each  $N^+P$  photo-diode to apply the principle described in Publication 1 to the above structure.

As shown in Fig. 56A, short wavelength light such as Blue is detected by the shallow  $N^+P$  photo-diode 201. Long wavelength 20 light such as Red is detected by the deep  $N^+P$  photo-diode 203 as shown in Fig. 56C. The medium wavelength light such as Green is detected by the  $N^+P$  photo-diode 202 locating in the depth of between the above two  $N^+P$  photo-diodes as shown in Fig. 56B.

Since the solid-state image pickup does not employ color 25 filters, spectra of color component output signals (R, G, B)

mutually become larger, thereby causing overlaps. This also presents a problem of difficulty in faithful color reproduction and an attempt to enhance image quality.

In addition, an increase in the number of pixels of a  
5 solid-state image pickup device to be incorporated in a recent digital still camera, a video movie camera, or the like has recently been pursued in earnest. Conversely, the area of a light-receiving section accounting for each pixel of the solid-state image pickup device has become smaller. Hence,  
10 photographing an image with the same sensitivity as that ever achieved becomes more difficult. Development of a color solid-state image pickup device which can simultaneously achieve enhanced sensitivity, color reproducibility, and a low noise characteristic without involvement of color signal  
15 separation computation processing is desired.

#### **Summary of the Invention**

The present invention aims at providing a color solid-state image pickup, especially an MOS color solid-state  
20 image pickup device, which is easy to manufacture, can ensure a wide area for light-receiving sections on the surface of a semiconductor substrates, obviates a necessity for color signal separation computation processing, and enables an easy attempt to enhance quality of a photographed image.

25 The present invention also aims at providing a color

solid-state image pickup device, especially a CCD color solid-state image pickup device, which enables an attempt to enhance sensitivity and image quality.

The present invention provides a color solid-state image pickup device comprising: a plurality of light-receiving sections being arranged on the surface of a semiconductor substrate in a two-dimensional array; complementary color filters which are stacked on all or portions of the plurality of light-receiving sections, each complementary color filter blocking incident light of one color of the three primary colors, to thereby permit transmission of incident light of remaining two colors of the three primary colors; at least first and second color signal detecting layers which have the complementary color filters stacked thereon and are formed so as to be separated in a depthwise direction of the light-receiving section, the first signal detecting layer detecting a color signal of one color of the light of two colors having passed through the complementary color filters, and the second signal detecting layer detecting a color signal of remaining one color of the light of two colors having passed through the complementary color filters; and a signal reading unit for reading the respective color signals in a distinguished manner, the signal reading unit being connected to the respective color signal detecting layers.

By means of such a configuration, incident light

components can be effectively utilized by use of complementary color filters, thereby enhancing sensitivity. Since primary color signals are obtained directly, a necessity for color signal separation computation processing is obviated. Further, use 5 of a color filter results in a reduction in overlaps existing between spectral sensitivity spectra of respective color signals, thereby further enabling faithful reproduction of colors. Enhanced image quality can also be attained.

There is provided the color solid-state image pickup 10 device, wherein a color signal of one color being different from two colors of the three primary colors, the two colors being detected by a first light-receiving section with the complementary color filter stacked thereon, is determined by subjecting, to interpolation processing, at least one detection 15 signal detected by at least one second light-receiving section which is provided around the first light-receiving section and, at least, detects the color signal of the one color being different from the two colors detected by the first light-receiving section. By means of such a configuration, 20 the three primary color signals are obtained at the respective light-receiving sections, thereby enabling reproduction of color information.

There is provided the color solid-state image pickup device, wherein three types of light-receiving sections are 25 arranged on the surface of the semiconductor substrate, that

is, the light-receiving section on which a yellow filter for blocking blue (B) light is stacked, the light-receiving section on which a cyan filter for blocking red (R) light is stacked, and the light-receiving section on which a magenta filter for  
5 blocking green (G) light is stacked.

By means of such a configuration, each light-receiving section can directly obtain signal components of two colors from among the three primary colors, R, G, and B. A signal component of one remaining color can be obtained by subjecting  
10 signal components of surrounding light-receiving sections to interpolation processing.

There is provided the color solid-state image pickup device, wherein two types of light-receiving sections are arranged on the surface of the semiconductor substrate, that is, the light-receiving section with a yellow filter stacked thereon, and the light-receiving section with a cyan filter stacked thereon.  
15

Even such a configuration enables each light-receiving section to directly obtain signal components of two colors from among the three primary colors, R, G, and B, and a signal component of one remaining color can be obtained by subjecting signal components of surrounding light-receiving sections to interpolation processing. Since a green (G) signal components can be obtained from all the light-receiving sections, a  
25 high-resolution image can be obtained by means of effecting

image processing while the green signal is taken as a luminance signal.

There is provided the color solid-state image pickup device, wherein two types of light-receiving sections are arranged on the surface of the semiconductor substrate, that is, the light-receiving section with a magenta filter stacked thereon, and the light-receiving section on which a green filter for permitting passage of green (G) light is stacked.

Even such a configuration enables obtaining of signal components of the three primary colors R, G, and B at positions of the respective light-receiving sections. A red (R) wavelength component and a blue (B) wavelength component, both passing through a magenta filter, are spaced away from each other. Hence, forming heavily-doped impurity layers for storing respective color signals so as to be separated from each other in a depthwise direction of the semiconductor substrate is facilitated. Further, an overlap existing between spectra of red and blue spectral sensitivities and the spectrum of a green spectral sensitivity obtained through the green filter can be diminished further. Therefore, an attempt to make more faithful color reproduction can be made.

There is provided the color solid-state image pickup device, wherein two types of light-receiving sections are arranged on the surface of the semiconductor substrate, that is, the light-receiving section with a magenta filter stacked

thereon, and the light-receiving section on which a transparent planarized film is stacked in place of a color filter.

By means of such a configuration, a white signal, i.e., a luminance signal, is obtained from the light-receiving section 5 on which a transparent planarized film is stacked in place of a color filter, thereby enabling an attempt to increase the sensitivity of a photographed image to a much greater extent.

There is provided the color solid-state image pickup device, wherein four types of light-receiving sections are 10 arranged on the surface of the semiconductor substrate, that is, the light-receiving section with a green filter stacked thereon, the light-receiving section with a yellow filter stacked thereon, the light-receiving section with a magenta filter stacked thereon, and the light-receiving section with 15 a cyan filter stacked thereon.

By means of such a configuration, signal electric charges can be read from respective light-receiving sections in sequence of color difference line, thereby enabling an attempt to speed up signal processing.

20 There is provided the color solid-state image pickup device, wherein an electric charge path formed from a heavily-doped impurity region, the region extending continuously up to the surface of the semiconductor substrate, is provided in a color signal detecting layer provided in the 25 semiconductor substrate from among the color signal detecting

layers.

By means of such a configuration, reading of color signals from a color signal detecting layer provided at a deep location of the semiconductor substrate becomes facilitated.

5 There is provided the color solid-state image pickup device, wherein a concentration gradient is set such that a doping level of the color signal detecting layer formed as a heavily-doped impurity region and a doping level of the electric charge path continually connected to the color signal detecting 10 layer increase as the layer and the path approach the signal reading unit.

By means of such a configuration, reading of signal electric charges from the color signal detecting layer is further facilitated, thereby preventing a failure to read remaining 15 signal electric charges.

There is provided the color solid-state image pickup device, wherein the depth of the first color signal detecting layer and the depth of the second color signal detecting layer are set in accordance with respective wavelengths of the light 20 of two colors having passed through the complementary color filters.

By means of such a configuration, the spectral characteristics of the respective color signal detecting layers can be rendered as originally set.

25 There is provided the color solid-state image pickup

device, wherein on-chip light gathering optical systems are provided on upper portions of the respective light-receiving sections, and one opening of each light-shielding film corresponds to each of the light-receiving sections. By means 5 of such a configuration, a loss in incident light is further reduced, whereby the utilization efficiency of incident light is further improved.

There is provided the color solid-state image pickup device, wherein the light-receiving sections are arranged in 10 a square solid pattern or a honeycomb pattern on the surface of the semiconductor substrate. The present invention can be applied to any one of these pixel arrangements.

There is provided the color solid-state image pickup device, wherein the signal reading unit is a vertical transfer 15 path; wherein the first color signal detecting layer is a first electric charge storage layer which reads, to the vertical transfer path, stored electric charges corresponding to the quantity of incident light from the light-receiving section, as the color signal; and wherein the second color signal 20 detecting layer is a second electric charge storage layer which reads, to the vertical transfer path, stored electric charges corresponding to the quantity of incident light from the light-receiving section, as the color signal.

By means of such a configuration, in a CCD color solid-state 25 image pickup device, incident light components can be

effectively utilized by use of complementary color filters, thereby enhancing sensitivity. Since primary color signals are obtained directly, a necessity for color signal separation computation processing is obviated. Further, use of a color 5 filter results in a reduction in overlaps existing between spectral sensitivity spectra of respective color signals, thereby further enabling faithful reproduction of colors.

Enhanced image quality can also be attained.

There is provided the color solid-state image pickup 10 device, wherein the depth of the first electric charge storage layer and the depth of the second electric charge storage layer are set in accordance with respective wavelengths of the light of two colors having passed through the complementary color filters; and wherein the depth of the electric charge storage 15 layer for storing electric charges corresponding to the quantity of blue (B) incident light ranges from 0.2 to 0.4  $\mu\text{m}$ ; the depth of the electric charge storage layer for storing electric charges corresponding to the quantity of green (G) incident light ranges from 0.4 to 0.8  $\mu\text{m}$ ; and the depth of the electric charge storage 20 layer for storing electric charges corresponding to the quantity of red (R) incident light ranges from 0.8 to 2.5  $\mu\text{m}$ . By means of such a configuration, in a CCD color solid-state image pickup device, depths of the respective electric charge storage layers are made optimum for storing electric charges according to the 25 quantity of R, G, and B incident light.

There is provided the color solid-state image pickup device, wherein the signal reading unit is a signal line.

By means of such a configuration, in an MOS color solid-state image pickup device, incident light components can 5 be effectively utilized by use of complementary color filters, thereby enhancing sensitivity. Since primary color signals are obtained directly, a necessity for color signal separation computation processing is obviated. Further, use of a color filter results in a reduction in overlaps existing between 10 spectral sensitivity spectra of respective color signals, thereby further enabling faithful reproduction of colors. Enhanced image quality can also be attained.

There is provided the color solid-state image pickup device, wherein the light-receiving sections store electric 15 charges in a PN junction section formed as a result of provision of heavily-doped impurity layers serving as the color signal detecting layers, in the semiconductor substrate; the electric charges are caused to discharge by means of photocarriers produced by incident light; and the quantity of change in 20 electric charges, which varies by means of electric discharge, is read as the color signal. By means of even such a configuration, in an MOS color solid-state image pickup device, sensitivity is enhanced, and primary color signals are obtained directly. Hence a necessity for color signal separation computation 25 processing is obviated. Further, use of a color filter results

in a reduction in overlaps existing between spectral sensitivity spectra of respective color signals, thereby further enabling faithful reproduction of colors. Enhanced image quality can also be attained.

5 There is provided the color solid-state image pickup device, wherein the depth of the first heavily-doped impurity layer and the depth of the second heavily-doped impurity layer are set in accordance with respective wavelengths of the light of two colors having passed through the complementary color  
10 filters; and wherein the depth of the heavily-doped impurity layer for detecting the blue (B) color signal ranges from 0.1 to 0.3  $\mu\text{m}$ ; the depth of said heavily-doped impurity layer for detecting the green (G) color signal ranges from 0.3 to 0.8  $\mu\text{m}$ ; and the depth of said heavily-doped impurity layer for  
15 detecting the red (R) color signal ranges from 0.8 to 2.5  $\mu\text{m}$ .

By means of such a configuration, in an MOS color solid-state image pickup device, depths of the respective heavily-doped impurity layers are made optimum for storing electric charges according to the quantity of R, G, and B incident  
20 light.

There is provided the color solid-state image pickup device, wherein an impurity region which is superimposed on the heavily-doped impurity layer for detecting a blue (B) color signal and establishes ohmic contact between the heavily-doped  
25 impurity layer and the signal line is formed deeper than the

heavily-doped impurity layer.

By means of such a configuration, in an MOS color solid-state image pickup device, electrical connection established at ohmic contacts is effected well, thereby 5 improving the reliability of the image pickup device.

#### **Brief Description of the Drawings**

Fig. 1 is a schematic surface view of a CCD color solid-state image pickup device of single plate type according 10 to a first embodiment of the invention;

Figs. 2A and 2B are descriptive views for reading signals from respective light-receiving sections of the CCD color solid-state image pickup device shown in Fig. 1;

Fig. 3 is a descriptive view for reproducing colors from 15 color signals read from the CCD color solid-state image pickup device shown in Fig. 1 by two reading operations;

Fig. 4A is a cross-sectional view taken along line a-a shown in Fig. 2A;

Fig. 4B is a cross-sectional view taken along line b-b 20 shown in Fig. 2A;

Fig. 4C is a cross-sectional view taken along line c-c shown in Fig. 2A;

Fig. 5 is a plan view showing four light-receiving sections (four pixels) of the CCD color solid-state image pickup device 25 shown in Fig. 1;

Fig. 6 is a view made by superimposing transfer electrodes on the pixels shown in Fig. 5;

Fig. 7 is a detailed view of the inside of an area enclosed by a circle VII shown in Fig. 6;

5 Fig. 8A is a view showing a relationship between a distance over which light has entered and traveled through a cyan filter Cy in a silicon substrate and a storage layer of the first embodiment;

10 Fig. 8B is a view showing a relationship between a distance over which light has entered and traveled through a yellow filter Ye in a silicon substrate and a storage layer of the first embodiment;

15 Fig. 8C is a view showing a relationship between a distance over which light has entered and traveled through a magenta filter Mg in a silicon substrate and a storage layer of the first embodiment;

20 Fig. 9A is a view showing a spectral sensitivity spectrum of a B signal and that of a G signal, both signals being produced by a light-receiving section with the cyan filter Cy stacked thereon;

Fig. 9B is a view showing a spectral sensitivity spectrum of the G signal and that of an R signal, both signals being produced by a light-receiving section with the yellow filter Ye stacked thereon;

25 Fig. 9C is a view showing a spectral sensitivity spectrum

of the B signal and that of the R signal, both signals being produced by a light-receiving section with the magenta filter Mg stacked thereon;

Fig. 10 is a schematic surface view of a CCD color  
5 solid-state image pickup device of single plate type according to a second embodiment of the invention;

Fig. 11 is a descriptive view for reproducing colors from color signals read from the CCD color solid-state image pickup device shown in Fig. 10 by two reading operations;

10 Fig. 12 is a plan view showing the pattern of an element isolation region corresponding to two horizontally-adjacent light-receiving sections (two pixels) of the CCD color solid-state image pickup device shown in Fig. 10;

Fig. 13 is a plan view showing four light-receiving  
15 sections (four pixels) of the CCD color solid-state image pickup device shown in Fig. 10;

Fig. 14A is a cross-sectional view taken along line a-a shown in Fig. 13;

Fig. 14B is a cross-sectional view taken along line b-b  
20 shown in Fig. 13;

Fig. 15A is a view showing a relationship between a distance over which light has entered and traveled through a cyan filter Cy in a silicon substrate and a storage layer of the second embodiment;

25 Fig. 15B is a view showing a relationship between a distance

over which light has entered traveled through a yellow filter  
Ye in a silicon substrate and a storage layer of the second  
embodiment;

Fig. 16 is a schematic surface view of a CCD color  
5 solid-state image pickup device of single plate type according  
to a third embodiment of the invention;

Fig. 17 is a descriptive view for reproducing colors from  
color signals read from the CCD color solid-state image pickup  
device shown in Fig. 16 by two reading operations;

10 Fig. 18 is a plan view showing a pattern of element  
isolation regions corresponding to two horizontally-adjacent  
light-receiving sections (two pixels) of the CCD color  
solid-state image pickup device shown in Fig. 16;

Fig. 19 is a plan view showing four light-receiving  
15 sections (four pixels) of the CCD color solid-state image pickup  
device shown in Fig. 16;

Fig. 20A is a cross-sectional view taken along line a-a  
shown in Fig. 19;

Fig. 20B is a cross-sectional view taken along line b-b  
20 shown in Fig. 19;

Fig. 21A is a view showing a relationship between a distance  
over which light has entered and traveled through a magenta  
filter Mg in a silicon substrate and a storage layer of the  
third embodiment;

25 Fig. 21B is a view showing a relationship between a distance

over which light has entered and traveled through a green filter G in a silicon substrate and a storage layer of the third embodiment;

Fig. 22 is a view showing a spectral sensitivity spectra 5 of the primary color signals produced by the color solid-state image pickup device of the third embodiment of the invention;

Fig. 23 is a schematic surface view of a CCD color solid-state image pickup device of single plate type according to a fourth embodiment of the invention;

10 Fig. 24 is a descriptive view for reproducing colors from color signals read from the CCD color solid-state image pickup device shown in Fig. 23 by two reading operations;

Fig. 25 is a plan view showing four light-receiving sections (four pixels) of the CCD color solid-state image pickup 15 device shown in Fig. 23;

Fig. 26A is a cross-sectional view taken along line a-a shown in Fig. 25;

Fig. 26B is a cross-sectional view take along line b-b shown in Fig. 25;

20 Fig. 27A is a view showing a relationship between a distance over which light has entered and traveled through a magenta filter Mg in a silicon substrate and a storage layer of the fourth embodiment;

Fig. 27B is a view showing a relationship between a distance 25 over which light has entered and traveled through a white filter

W in a silicon substrate and a storage layer of the fourth embodiment;

Fig. 28 is a view showing a spectral sensitivity spectra of the primary color signals produced by the color solid-state 5 image pickup device of the fourth embodiment;

Fig. 29 is a schematic surface view of a CCD color solid-state image pickup device of single plate type according to a fifth embodiment of the invention;

Fig. 30 is a schematic surface view of a CMOS color 10 solid-state image pickup of single plate type according to a sixth embodiment of the invention;

Fig. 31A is a cross-sectional view taken along line XXXIa-XXXIa shown in Fig. 30;

Fig. 31B is a cross-sectional view take along line 15 XXXIb-XXXIb shown in Fig. 30;

Fig. 32A is a cross-sectional view taken along line XXXIIa-XXXIIa shown in Fig. 30;

Fig. 32B is a cross-sectional view take along line XXXIIb-XXXIIb shown in Fig. 30;

20 Fig. 33 is an equivalent circuit diagram of amplifiers shown in Figs. 31A, 31B, 32A, and 32B [i.e., amplifier circuits (source follower amplifiers)];

Fig. 34A is a graph showing the potential profile of a light-receiving section with a Cy filter stacked thereon shown 25 in Fig. 30;

Fig. 34B is a graph showing the potential profile of a light-receiving section with a Mg filter stacked thereon shown in Fig. 30;

5 Fig. 35A is a graph showing the potential profile of a light-receiving section with a Ye filter stacked thereon shown in Fig. 30;

Fig. 35B is a graph showing the potential profile of a light-receiving section with a G filter stacked thereon shown in Fig. 30;

10 Fig. 36A is a graph showing a spectral characteristic of the light-receiving section with a Cy filter stacked thereon shown in Fig. 30;

Fig. 36B is a graph showing a spectral characteristic of the light-receiving section with a Mg filter stacked thereon shown in Fig. 30;

15 Fig. 37A is a graph showing a spectral characteristic of the light-receiving section with a Ye filter stacked thereon shown in Fig. 30;

Fig. 37B is a graph showing a spectral characteristic of the light-receiving section with a G filter stacked thereon shown in Fig. 30;

20 Fig. 38 is a descriptive view reproducing color information by means of obtaining three color signals R, G, and B at the positions of the light-receiving sections with 25 the color filters (Cy, Mg, Ye, G) stacked thereon shown in Fig.

30;

Fig. 39 is a two-dimensional plan view corresponding to four pixels of the light-receiving sections with Cy, Mg, Ye, G filters stacked thereon of the color solid-state image pickup

5 device shown in Fig. 30;

Fig. 40A is a cross-sectional view of the CMOS color solid-state image pickup shown in Fig. 31A on which a microlens, a light-shielding film, or the like are stacked;

Fig. 40B is a cross-sectional view of the CMOS color solid-state image pickup shown in Fig. 31B on which a microlens, a light-shielding film, or the like are stacked;

Fig. 41A is a cross-sectional view of the CMOS color solid-state image pickup shown in Fig. 32A on which a microlens, a light-shielding film, or the like are stacked;

15 Fig. 41B is a cross-sectional view of the CMOS color solid-state image pickup shown in Fig. 32B on which a microlens, a light-shielding film, or the like are stacked;

Fig. 42 is a schematic surface view of a CMOS color solid-state image pickup of single plate type according to a 20 seventh embodiment of the invention;

Fig. 43 is a descriptive view reproducing color information by means of obtaining three color signals R, G, and B at the positions of the light-receiving sections with the color filters (Cy, Ye) stacked thereon shown in Fig. 42;

25 Fig. 44 is a two-dimensional plan view corresponding to

four pixels of the light-receiving sections with Cy, Ye filters stacked thereon of the color solid-state image pickup device shown in Fig. 42;

Fig. 45 is a schematic surface view of a CMOS color 5 solid-state image pickup of single plate type according to an eighth embodiment of the invention;

Fig. 46 is a descriptive view reproducing color information by means of obtaining three color signals R, G, and B at the positions of the light-receiving sections with 10 the color filters (Mg, G) stacked thereon shown in Fig. 45;

Fig. 47 is a two-dimensional plan view corresponding to four pixels of the light-receiving sections with Mg, G filters stacked thereon of the color solid-state image pickup device shown in Fig. 45;

15 Fig. 48 is a graph showing a spectral characteristic of the color solid-state image pickup device shown in Fig. 45;

Fig. 49 is a schematic surface view of a CMOS color solid-state image pickup of single plate type according to a ninth embodiment of the invention;

20 Fig. 50 is a descriptive view reproducing color information by means of obtaining three color signals R, G, and B at the positions of the light-receiving sections with the filters (Mg, W) stacked thereon shown in Fig. 49;

Fig. 51 is a cross-sectional schematic view taken along 25 line LI-LI shown in Fig. 49;

Fig. 52 is a cross-sectional view of the CMOS color solid-state image pickup shown in Fig. 51 on which a microlens, a light-shielding film, or the like are stacked;

Fig. 53 is a view showing the potential profile of the 5 light-receiving section on which a W filter shown in Fig. 49 is stacked;

Fig. 54 is a graph showing a spectral characteristic of the CMOS color solid-state image pickup device shown in Fig. 49;

10 Fig. 55 is a descriptive view of a related-art color solid-state image pickup device; and

Figs. 56A to 56C are descriptive views of a related-art color solid-state image pickup device.

15 **Detailed Description of the Invention**

Embodiments of the invention will be described hereinbelow by reference to the drawings.

(First Embodiment)

Fig. 1 is a schematic surface view of a CCD color 20 solid-state image pickup of single plate type according to a first embodiment of the invention. In the CCD color solid-state image pickup, a plurality of light-receiving sections 1, each having a cross-sectional structure to be described in detail later, are formed in an array on the surface of a semiconductor 25 substrate 10. In an illustrated example, each light-receiving

section 1 is depicted as a rhombus.

The arrangement of pixels employed in the present embodiment corresponds to the arrangement of pixels described in JP-A-10-136391; that is, a so-called honeycomb pixel arrangement in which the respective light-receiving sections 1 are offset at half a pitch in both the vertical and horizontal directions. A vertical transfer path [e.g., a vertical charge-coupled device (VCCD)] 2 (signal reading unit) is formed between adjacent light-receiving sections 1, and signal electric charges read to the vertical transfer path 2 from the respective light-receiving sections 1 are transferred, in a meandering manner, to a horizontal transfer path [e.g., a horizontal charge-coupled device (HCCD)] 3 located at a lower position on the drawing.

Any of a yellow (Ye) filter, a cyan (Cy) filter, and a magenta (Mg) filter, all being filters of a complementary color system, are stacked on surfaces of the respective light-receiving sections 1. The Ye filter permits passage of light having green (G) and red (R) wavelength components; the Cy filter permits passage of light having blue (B) and the green (G) wavelength components; and the Mg filter permits passage of light having the red (R) and blue (B) wavelength components.

Each light-receiving section 1 of the embodiment has a cross-sectional structure which will be described in detail later. Therefore, the light-receiving section 1 can

simultaneously store, from G+R light having passed through the Ye filter, a signal electric charge corresponding to the quantity of G and a signal electric charge corresponding to the quantity of R and separately read the thus-stored signal electric charges

5 to the vertical transfer path 2. The light-receiving section 1 can simultaneously store, from B+G light having passed through the Cy filter, a signal electric charge corresponding to the quantity of B and a signal electric charge corresponding to the quantity of G and separately read the thus-stored signal

10 electric charges to the vertical transfer path 2. Further, the light-receiving section 1 can simultaneously store, from R+B light having passed through the Mg filter, a signal electric charge corresponding to the quantity of R and a signal electric charge corresponding to the quantity of B and separately read

15 the thus-stored signal electric charges to the vertical transfer path 2.

For instance, as shown in Fig. 2A, reading of a G signal from the light-receiving section 1 having the Ye filter, reading of a B signal from the light-receiving section having the Cy filter, and reading of an R signal from the light-receiving section having the Mg filter are performed by a first reading operation. As shown in Fig. 2B, reading of an R signal from the light-receiving section 1 having the Ye filter, reading of a G signal from the light-receiving section having the Cy filter, and reading of a B signal from the light-receiving

section having the Mg filter are performed by a second reading operation.

Specifically, reading of signal electric charges from the light-receiving sections, transfer of the signal electric charges through the VCCD, and transfer of the signal electric charges through the HCCD are performed twice over the entire light-receiving area, whereby two primary-color signal components can be obtained from one light-receiving section.

10 A deficient one-color signal in each light-receiving section is determined as a mean value of signals from surrounding pixels.

Specifically, as shown in Fig. 3, the B signal read by the first reading operation and the G signal read by the second reading operation are used for reproducing a color of the location enclosed by a circle. For instance, a mean value of a total 15 of six R signals (R signals from surrounding three pixels  $\times$  2) is used for determining a deficient R signal. A color of the position enclosed by the circle is reproduced by means of the thus-determined R, G, and B signals pertaining to the position enclosed by the circle.

20 Fig. 4A is a cross-sectional view taken along line a-a shown in Fig. 2; Fig. 4B is a cross-sectional view taken along line b-b shown in Fig. 2; and Fig. 4C is a cross-sectional view taken along line c-c shown in Fig. 2. In these cross-sectional views, a complementary filter and a microlens provided thereon 25 are omitted from the drawings.

The CCD color solid-state image pickup device of the present embodiment separates the R, G, and B color signal components by utilization of an optical characteristic of the silicon substrate. Specifically, the light absorption 5 coefficient of a silicon substrate changes across a visible range from light of long wavelength (R) to light of short wavelength (B). Hence, light in a wavelength range having a large light absorption coefficient is absorbed by a shallow area of the silicon substrate, and hence the light hardly reaches 10 a deep area of the silicon substrate. Conversely, light in a wavelength range having a small light absorption coefficient reaches a deep region of the silicon substrate. Therefore, the light can be subjected to photoelectric conversion even at the deep area of the silicon substrate.

15 In relation to the optical characteristic of the silicon substrate, the paper entitled "A Planar Silicon Photosensor with an Optimal Spectral Response for Detecting Printed Material" by Paul A. Gary and John G. Linvill, IEEE TRANSACTIONS ON ELECTRON DEVICES, Vol. ED-15, No. 1, January, 1968 describes 20 dependence of a photoelectric conversion characteristic of a photodiode on the depthwise position of a silicon substrate as well as on the wavelength of incident light. Further, a CMOS image sensor employing this principle is described in USP No. 5965875.

25 In Fig. 4A, a light-receiving section, on which the cyan

(Cy) filter is stacked and which stores blue (B) and green (G) signal electric charges, is formed in an n-type semiconductor substrate 10. A P-well layer 11 is formed on the surface of the semiconductor substrate 10, and two N<sup>+</sup> layers 12, 13 (color signal detecting layers) are formed within the P well layer 11 so as to be separated from each other in the depthwise direction.

The signal electric charges primarily produced from an incident light component of short wavelength light (e.g., B) are stored in the N<sup>+</sup> layer 12 provided at the most shallow position with respect to the depthwise direction of the semiconductor substrate 10. The N<sup>+</sup> layer 12 constituting the signal electric charge storage section extends up to a position below a read gate electrode 6a (dopant [phosphorous or arsenic (P or As)] content is about  $5 \times 10^{16-17}/\text{cm}^3$ , and the depth of the N<sup>+</sup> layer is 0.2 to 0.4  $\mu\text{m}$ , wherein the depth is dependent on the dopant content, and the same also applies to any counterparts in the following descriptions}. Therefore, only the electric charges derived primarily from the light of short wavelength pass through a gate section and are read to the vertical transfer path 2.

The N<sup>+</sup> layer (n2) 13 provided at a position slightly deeper than the N<sup>+</sup> layer 12 has, at an end section thereof, an N<sup>+</sup> region (i.e., a charge path) 13a which extends up to the surface of the semiconductor substrate 10. This charge path 13a extends up to a position below a read gate electrode 7a formed from

a portion of the transfer electrode. The signal electric charges formed from light of intermediate wavelength (e.g., G) are stored in the N<sup>+</sup> layer 13. The N<sup>+</sup> layer 13 constituting the signal electric charge storage section (dopant content is 5 about  $5 \times 10^{16-17}/\text{cm}^3$  at a depth of 0.4 to 0.8  $\mu\text{m}$ ) extends up to a position below the read gate electrode 7a. As a result, the electric charges derived primarily from the light of intermediate wavelength (G) pass through a gate section and are read to the vertical transfer path 2.

10 In Fig. 4B, a light-receiving section, on which the yellow (Ye) filter is stacked and which stores green (G) and red (R) signal electric charges, is formed within the P well layer 11 as two N<sup>+</sup> layers 13', 14 (color signal detecting layers) which are separated from each other in a depthwise direction.

15 An end of the N<sup>+</sup> layer (n2') 13' extends to a position below the read gate electrode 7a constituting a portion of the transfer electrode. The signal electric charges formed from light of intermediate wavelength (e.g., G) are stored in the N<sup>+</sup> layer 13'. The N<sup>+</sup> layer 13' constituting the signal electric 20 charge storage section (dopant content is about  $5 \times 10^{16-17}/\text{cm}^3$  at a depth of 0.2 to 0.8  $\mu\text{m}$ ) extends up to a position below the read gate electrode 7a. As a result, the electric charges derived primarily from the light of intermediate wavelength (G) pass through a gate section and are read to the vertical 25 transfer path 2.

The structure of the  $N^+$  layer 13 shown in Fig. 4A may be adopted in lieu of the  $N^+$  layer 13'. Even if the electric charge storage layer 13' is formed as an  $N^+$  layer up to a depth of 0.8  $\mu m$  or the like from the surface as in the case of the 5 embodiment, the yellow (Ye) filter is stacked on the surface of the electric charge layer. Of the incident light, B light is blocked by the yellow filter, and hence B signal electric charges are not stored in the electric charge storage layer 13'.

10 The  $N^+$  layer (n3) 14 formed at a deep position has, at an end section thereof, an  $N^+$  region (i.e., a charge path) 14a which extends up to the surface of the semiconductor substrate 10. This  $N^+$  region 14a extends up to a position below the read gate electrode 6a formed from a portion of the transfer electrode. 15 The signal electric charges formed from light of long wavelength (e.g., R) are stored in the  $N^+$  layer 14. The  $N^+$  layer 14 constituting the signal electric charge storage section (dopant content is about  $5 \times 10^{16-17}/cm^3$  at a depth of 0.8 to 2.5  $\mu m$ ) extends up to a position below the read gate electrode 6a. As 20 a result, the electric charges derived primarily from the light of long wavelength (R) pass through the gate section and are read to the vertical transfer path 2.

In Fig. 4C, a light-receiving section, on which the magenta (Mg) filter is stacked and which stores blue (B) and red (R) 25 signal electric charges, is formed within the P well layer 11

as two  $N^+$  layers 12, 14 (color signal detecting layers) which are separated from each other in a depthwise direction.

Signal electric charges derived primarily from an incident light component of short wavelength light (B) are stored 5 in the  $N^+$  layer 12 located at the surface and read to the vertical transfer path 2 by way of the gate section. Signal electric charges derived from light of long wavelength (e.g., R) are stored in the  $N^+$  layer (n3) 14 formed at a deep position and read to the vertical transfer path 2 by way of the gate section.

10 A shallow  $P^+$  layer 15 is provided in a portion of the surface of the semiconductor substrate 10 equipped with three types of storage sections 12, 13 (13'), and 14 formed at different depths. Further, an  $SiO_2$  film 16 is provided on the top surface of the semiconductor substrate 10. A dopant (boron) content 15 of the  $P^+$  layer 15 is about  $1 \times 10^{18}/cm^3$ , and the  $P^+$  layer 15 has a depth of about 0.1 to 0.2  $\mu m$ . The dopant content contributes to a reduction in a defect level of an oxide film-semiconductor boundary surface. Accordingly, the storage section 12 located at the most shallow position in the depthwise direction of the 20 semiconductor substrate 10 assumes a  $P^+N^+P$  structure.

As mentioned above, the CCD color solid-state image pickup device of the embodiment as a whole assumes a  $P^+(N^+P)(N^+P)$  structure. Two types of storage sections ( $N^+$  layers) of different depths are formed so as to be separated from each 25 other with a P region (which will become a potential barrier)

being sandwiched therebetween in the depthwise direction of the substrate. The boron content of the P region located between the N<sup>+</sup> layers is set to  $1 \times 10^{14-16}/\text{cm}^3$ .

Preferably, the dopant content of the storage section 5 formed from the N<sup>+</sup> layers and that of the electric charge path are preferably given a concentration gradient so as to become higher toward the read gate section than at the light incidence region close to the center of the storage section. As a result, reading of the signal electric charges becomes easy, and 10 retention of unread electric charges can be prevented.

In the embodiment, double-layer storage sections are formed in any of the light-receiving sections 1 in the depthwise direction of the substrate, and there is provided no N<sup>+</sup> layer assigned to light of wavelength which is beyond the range of 15 wavelengths for which signal electric charges are stored.

However, a complementary color filter is stacked on each light-receiving section 1, and hence one of the R, G, and B color signals is blocked by the complementary color filter, to thereby fail to reach the silicon substrate. Consequently, 20 even when the N<sup>+</sup> layers 12, 13, and 14, each having a triple-layer structure, are provided in the respective light-receiving sections 1 with a view toward achievement of a commonality of mask patterns constituting the respective N<sup>+</sup> layers, signal electric charges are not stored in the N<sup>+</sup> layer assigned to 25 light of a wavelength (i.e., color) which does not reach the

silicon substrate. However, when each light-receiving section is given a triple structure, unwanted electric charges are considered to remain in the storage section (i.e., the  $N^+$  layer) from which no electric charges are read. For this reason, a 5 positive voltage pulse is preferably applied to the substrate before the next photographing operation in order to wipe away unwanted electric charges.

Fig. 5 is a plan view showing a pattern of four pixels of the light-receiving section 1 shown in Fig. 1 and a pattern 10 of the vertical transfer path 2 laid between the light-receiving sections 1. The light-receiving sections 1 are partitioned from each other by means of rhombus element isolation regions 15. Of four sides of the rhombus, gate sections 4a, 4b are formed in two right sides where the element isolation region 4 is broken. Of the signal electric charges stored in the respective storage sections 12, 13, and 14, signal electric charges (see Fig. 2A) which are to be read by the first reading operation are read 20 to the vertical transfer path 2 by way of the gate section 4a. The signal electric charges (see Fig. 2B) which are to be read by the second reading operation are read to the vertical transfer path 2 by way of the gate section 4b.

Fig. 6 is a view made by superimposing transfer electrodes on the pixels shown in Fig. 5, and Fig. 7 is a detailed view of the inside of an area enclosed by a circle VII shown in Fig. 25 6. The transfer electrode formed from a two-layer polysilicon

structure is provided so as to cover the vertical transfer path

2. Four transfer electrodes 5, 6, 7, and 8 are assigned to one light-receiving section 1. As a result, the electrodes constitute a so-called CCD which can read all pixels (i.e.,

5 a CCD capable of performing progressive operation).

Figs. 8A, 8B, and 8C are conceptual renderings for describing the fact that depths of the silicon substrate to which the light signals having passed through the complementary color filters Cy, Ye, and Mg travel change according to

10 wavelengths of the light signals. Specifically, the B light, having the shortest wavelength, is absorbed by the most shallow region of the silicon substrate, thereby generating photoelectric charges. The thus-generated photoelectric

charges are stored in the first storage section n1. The G light,

15 having an intermediate wavelength, reaches a position deeper than that to which the B light has arrived, and hence a large number of produced electric charges are stored in a storage section n2 (n2') located at the intermediate depth. Similarly, electric charges produced by the R light, having the longest

20 wavelength, are stored in a storage region n3 located at the deepest location of the silicon substrate.

A P region, which is to act as a potential barrier, exists between the signal charge storage sections n1, n2 and between the signal charge storage sections n2 (n2'), n3. Signal charges

25 (i.e., electrons) having developed in the P region are allocated

to any of the adjacent charge storage sections [n1, n2 (n2'), n3] along a potential profile.

Fig. 9A is a view showing a spectral sensitivity spectrum of the B signal and that of the G signal, both signals being produced by the light-receiving section with the cyan (Cy) filter stacked thereon. Fig. 9B is a view showing a spectral sensitivity spectrum of the G signal and that of the R signal, both signals being produced by the light-receiving section with the yellow (Ye) filter stacked thereon. Fig. 9C is a view showing a spectral sensitivity spectrum of the B signal and that of the R signal, both signals being produced by the light-receiving section with the magenta (Mg) filter stacked thereon.

According to the configuration of the light-receiving section of the embodiment, an overlap existing between the spectral sensitivity spectra of the respective signal components B, G, and R becomes smaller. Hence, more faithful colors can be reproduced by subjecting the signal components produced by the light-receiving sections to image processing, thereby enabling an attempt to achieve higher image quality.

The CCD color solid-state image pickup device of the embodiment increases the utilization efficiency of incident light through use of complementary color filters, thereby enhancing sensitivity. Moreover, the respective light-receiving sections can distinguish color signals and directly read primary color signals, thereby obviating a

necessity for color signal separation computation processing.

This embodiment has described the solid-state image pickup device in which the light-receiving sections 1 are arranged in a so-called honeycomb pattern. However, the 5 embodiment can also be applied to a solid-state image pickup device in which the light-receiving sections 1 are arranged in a square grid pattern.

(Second Embodiment)

Fig. 10 is a schematic surface view of a CCD color 10 solid-state image pickup device of single plate type according to a second embodiment of the invention. In the following embodiment, unless otherwise specified, the dopant content of the  $N^+$  layer or the like and the depth of the storage layer are the same as those described in connection with the first 15 embodiment.

In Fig. 10, a light-receiving section 21 is represented as a rectangle, and a plurality of light-receiving sections 21 are arranged in an array pattern. In this embodiment, the light-receiving sections 21 are arranged in a square grid pattern. 20 A vertical transfer path 22 (signal reading unit) is formed between horizontally-adjacent light-receiving sections 21. Signal charges read from the light-receiving section 21 to the vertical transfer path 22 are transferred to a horizontal transfer path 23 provided at a downward location.

25 Complementary color filters; that is, the Ye filter and

the Cy filter, are stacked alternately on the light-receiving sections 21 of the present embodiment with respect to the vertical and horizontal directions.

Green (G) signal electric charges and red (R) signal electric charges are distinctively stored in the light-receiving sections 21 with the Ye filters stacked thereon. The G signal and the R signal are separately read to the vertical transfer path 22. Moreover, the green (G) signal electric charges and blue (B) signal electric charges are stored separately in the light-receiving sections 21 with the Cy filters stacked thereon. The G signal and the B signal are separately read to the vertical transfer path 22.

As mentioned above, according to the present embodiment, the G signals are produced by all the light-receiving sections 21, and the R and B signals are alternately produced by the light-receiving sections 21 that are arranged vertically and horizontally. More specifically, each of the light-receiving sections 21 is deficient of either the R color signal or the B color signal. However, the deficient color signal is determined as a mean value of peripheral pixel signals.

As shown in Fig. 11, the G signal read through the first reading operation and the R signal read through the second reading operation are used for reproducing a color of the area enclosed by, e.g., a circle. A mean value of B signals of four peripheral signals from the adjacent pixels is used as a

deficient B signal.

Fig. 12 is a plan view showing two pixels of the light-receiving section 21 and a vertical transfer path laid between horizontally-adjacent light-receiving sections, both 5 pertaining to the present embodiment. Each light-receiving section is surrounded by a C-shaped element isolation region 24. Signal electric charges are read to the vertical transfer path 22 from a gate section 24a where the element isolation region 24 is not present.

10 Fig. 13 is a view showing a transfer electrode of a color solid-state image pickup device of the embodiment. In the embodiment, transfer electrodes 25, 26, and 27 have a triple-layer polysilicon structure and are constituted of interline CCDs which can read all pixels. The second 15 polysilicon electrode 26 and the third polysilicon electrode 27 constitute read gate electrodes. When a read voltage is applied to the respective read gate electrodes, a signal electric charge is read to the vertical transfer path 22 from the corresponding signal electric charge storage section.

20 Fig. 14A is a cross-sectional view taken along line a-a shown in Fig. 13; that is, a cross-sectional view of a light-receiving section with the Cy filter stacked thereon; and Fig. 14B is a cross-sectional view taken along line b-b shown in Fig. 13; that is, a cross-sectional view of a 25 light-receiving section with a Ye filter stacked thereon.

In Fig. 14A, a P well layer 31 is formed on the surface of an n-type semiconductor substrate 30 of the color solid-state image pickup device of the embodiment. Signal electric charge storage layers 32, 33 (color signal detecting layers) are formed 5 from a two-layer N<sup>+</sup> structure within the P well layer 31 so as to be separated from each other in a depthwise direction.

A storage layer (n1) 32 provided in a surface section extends up to a position below the read gate electrode 26a formed from a portion of the transfer electrode. The signal electric 10 charges primarily produced from an incident light component of short wavelength (e.g., B) are stored in the storage layer 32 provided at the most shallow position with respect to the depthwise direction of the semiconductor substrate 30. In this structure, only the electric charges stored in the storage layer 15 32; that is, the electric charges produced primarily from light of short wavelength, are read to the vertical transfer path 22.

The second storage layer (n2) 33 has, at an end section thereof, an N<sup>+</sup> region (i.e., a charge path) 33a which extends 20 up to the surface of the semiconductor substrate 30. This N<sup>+</sup> region 33a extends up to a position below a read gate electrode 27a formed from a portion of the transfer electrode. The signal electric charges formed from light of intermediate wavelength (e.g., G) are stored in the this storage layer 33. In this 25 structure, the electric charges stored in the storage layer

33; that is, the electric charges produced primarily from the light of intermediate wavelength (G), are read to the vertical transfer path 22.

A light-shielding film 40 having openings to oppose a light-receiving surface of the light-receiving section is placed on top of the light-receiving section in which the storage layers 32, 33 of such a configuration are formed. A Cy filter 41 and a microlens 42 are stacked on the light-shielding film 40. Light is gathered by the microlens 42, and the incident light—for which light of a red (R) wavelength is blocked by the Cy filter 41—enters the light-receiving section by way of an opening 40a of the light-shielding film 40.

As in the case of the first embodiment, the P<sup>+</sup> layer 15 and the SiO<sub>2</sub> film 16 are provided on the top surface of the semiconductor substrate 30.

In Fig. 14B, signal electric charge storage layers 34, 35 (color signal detecting layers) are formed from an N<sup>+</sup> layer of two-layer structure within the P well layer 31, which is formed on the surface of the n-type semiconductor substrate 30, so as to be separated from each other in the depthwise direction.

The storage layer (n2') 34 of the surface section is formed up to about the same depth as that of the storage layer 33 shown in Fig. 14A. The end section of the storage layer 34 extends 25 up to a position below the read gate electrode 26a formed from

a portion of the transfer electrode 26. The signal electric charges primarily produced from an incident light component of intermediate wavelength (e.g., G) are stored in the end section of the storage layer 34. In this structure, only the 5 electric charges stored in the storage layer 34; that is, the electric charges produced primarily from light of intermediate wavelength, are read to the vertical transfer path 22.

The storage layer (n3) 35 formed at a deep position of the P well layer 31 has, at an end section thereof, an N<sup>+</sup> region 10 (i.e., a charge path) 35a which extends up to the surface of the semiconductor substrate 30. This N<sup>+</sup> region 35a extends up to a position below the read gate electrode 27a formed from a portion of the transfer electrode 27. The signal electric charges formed from light of long wavelength (e.g., R) are stored 15 in the this storage layer 35. In this structure, only the electric charges stored in the storage layer 35 are read to the vertical transfer path 22.

An opening 40b of the light-shielding film 40 is also placed also on the light-receiving section in which the storage 20 layers 34, 35 of such a configuration are formed. A Ye filter 43 and a microlens 44 are stacked on the opening 40b. Light is gathered by the microlens 44, and the incident light—for which light of a blue (B) wavelength is blocked by the Ye filter 43—enters the light-receiving section by way of the opening 25 40b of the light-shielding film 40. Similarly, a P<sup>+</sup> layer 15

and a  $\text{SiO}_2$  film 16 are formed on the top surface of the semiconductor substrate 30.

The storage layer 34 of the embodiment is distributed up to the surface of the substrate. However, light 5 corresponding to B light of short wavelength is blocked by the Ye filter. Hence, the storage layer 34 has no sensitivity against incident B light. Therefore, no particular restrictions are imposed on the distribution of the storage layer 34 in a depth direction. The storage layer 34 may be 10 formed in the same structure as that of the storage layer 33 shown in Fig. 14A (i.e., a structure in which the storage layer is not distributed up to the neighborhood of the surface of the semiconductor substrate).

Figs. 15A and 15B are conceptual renderings for the 15 phenomenon that, in the solid-state image pickup device of the embodiment, distances over which the light signals having passed through the Cy filter 41 and the Ye filter 43 travel in the depthwise direction of the silicon substrate change according to wavelengths of the light signals.

As shown in Figs. 15A, in the light-receiving section 20 on which the Cy filter 41 for blocking red (R) light is stacked, blue (B) light having the shortest wavelength is absorbed in the most shallow region of the silicon substrate, whereby electric charges corresponding to the quantity of B light are 25 generated and then stored in the first storage layer n1. The

green (G) light of an intermediate wavelength reaches a position deeper than that at which the blue (B) light arrives, and hence large portions of produced electric charges are stored in the storage layer n2.

5 As shown in Fig. 15B, in the light-receiving section on which the Ye filter 43 for blocking the blue (B) light is stacked, green (G) light of intermediate wavelength is stored in the storage layer n2'. Similarly, electric charges produced from the R light of longest wavelength are stored in the storage 10 layer n3 located at the deepest location of the silicon substrate.

In this way, even the CCD color solid-state image pickup device of the embodiment can realize an attempt to enhance sensitivity by increasing the utilization efficiency of 15 incident light through use of the Cy and Ye filters of the filters of complementary color system. Moreover, the respective light-receiving sections can read primary color signals in a distinguishable manner, thereby obviating a necessity for color signal separation computation processing. Therefore, an 20 attempt can be made to realize faithful color reproduction and enhance image quality. Further, all the light-receiving sections can produce a green signal, and hence a high-resolution image can be obtained while the green signal is used as luminance information.

25 The embodiment has described a solid-state image pickup

device having the light-receiving sections 21 arranged in a square grid pattern. The embodiment can be readily applied to a solid-state image pickup device having the light-receiving sections 21 arranged in a so-called honeycomb pattern.

5 (Third Embodiment)

Fig. 16 is a schematic surface view of a CCD color solid-state image pickup device of single plate type according to a third embodiment of the invention. In the drawing, a light-receiving section 51 is represented by a rectangle, and 10 a plurality of light-receiving sections 51 are arranged in an array. In the embodiment, the light-receiving sections 51 are arranged in a square grid pattern. A vertical transfer path 52 (signal reading unit) is formed between horizontally-adjacent light-receiving sections 51. Signal 15 electric charges read from the light-receiving section 51 to the vertical transfer path 52 are transferred to a horizontally transfer path 53 placed at a downward position.

A green (G) filter, which is one of the filters of primary colors, and a magenta (Mg) filter, which is one of the filters 20 of the complementary color system, are alternately stacked on the light-receiving sections 51 of the present embodiment in both the vertical and horizontal directions. In the embodiment, incident light components which have not been blocked by the color filters (G, Mg) are read independently as signal components 25 of the primary color system (R, G, B).

Specifically, B and R signals are output from the light-receiving section 51 with the Mg filter stacked thereon. Therefore, the primary color signal component of one color (G) is output from the light-receiving sections 51 having the G 5 filter by twice performing operations for receiving electric charges from the light-receiving sections and transferring the thus-read electric charges to the VCCD and HCCD. Further, two primary color signal components of two colors (R, B) are output from the light-receiving section having the Mg filter.

10 Of the three primary colors, only one color (G) component is output from the light-receiving section 51 with the G filter stacked thereon. As shown in Fig. 17, G signals (a first signal is G1, and a second signal is G2) read through two reading operations are used at this light-receiving position while being 15 added together. A remaining R color is obtained by averaging peripheral R signals, and a remaining B color is obtained by averaging peripheral B signals.

Of the three primary colors, two colors (R, B) are obtained from the light-receiving sections with the Mg filter stacked 20 thereon. Four peripheral G1 signals and four peripheral G2 signals are used for determining the remaining G signal.

Fig. 18 is a plan view showing two pixels of the light-receiving section 51 and the vertical transfer path laid between the horizontally-adjacent light-receiving sections, 25 both pertaining to the present embodiment. Each

light-receiving section is surrounded by a C-shaped element isolation region 54. Signal electric charges are read to the vertical transfer path 52 from a gate section 54a where the element isolation region 54 is not present.

5 Fig. 19 is a view showing a transfer electrode of a color solid-state image pickup device of the embodiment. In the embodiment, transfer electrodes 55, 56, and 57 have a triple-layer polysilicon structure and constitute interline CCDs which can read all pixels. The second polysilicon 10 electrode 56 and the third polysilicon electrode 57 constitute read gate electrodes. When a read voltage is applied to the respective read gate electrodes, a signal electric charge is read to the vertical transfer path 52 from the corresponding signal electric charge storage section.

15 Fig. 20A is a cross-sectional view taken along line a-a' shown in Fig. 19; that is, a cross-sectional view of a light-receiving section with the Mg filter stacked thereon; and Fig. 20B is a cross-sectional view taken along line b-b' shown in Fig. 19; that is, a cross-sectional view of a 20 light-receiving section with a G filter stacked thereon.

In Fig. 20A, a P well layer 61 is formed on the surface of an n-type semiconductor substrate 60 of the color solid-state image pickup device of the embodiment. Signal electric charge storage layers 62, 63 (color signal detecting layers) are formed 25 from a two-layer N<sup>+</sup> structure within the P well layer 61 so

as to be separated from each other in a depthwise direction.

The storage layer (n1) 62 provided in a surface section extends up to a position below the read gate electrode 56a formed from a portion of the transfer electrode. The signal electric charges primarily produced from an incident light component of short wavelength (e.g., B) are stored in the storage layer 62 provided at the most shallow position with respect to the depthwise direction of the semiconductor substrate 60. In this structure, only the electric charges stored in the storage layer 62; that is, the electric charges produced primarily from light of short wavelength, are read to the vertical transfer path 52.

The second storage layer (n3) 63 has formed at a deep location, at an end section thereof, an N<sup>+</sup> region (i.e., a charge path) 63a which extends up to the surface of the semiconductor substrate 60. This N<sup>+</sup> region 63a extends up to a position below a read gate electrode 57a formed from a portion of the transfer electrode. The signal electric charges formed from light of long wavelength (e.g., R) are stored in the this storage layer 63. In this structure, the electric charges stored in the storage layer 63; that is, the electric charges produced primarily from the light of long wavelength (R), are read to the vertical transfer path 52.

A light-shielding film 66 having openings 66a to oppose a light-receiving surface of the light-receiving section is

placed on top of the light-receiving section in which the storage layers 62, 63 of such a configuration are formed. A Mg filter 67 and a microlens 68 are stacked on the light-shielding film 66. Light is gathered by the microlens 68, and the incident 5 light—for which light of a green (G) wavelength is blocked by the Mg filter 67—enters the light-receiving section by way of the opening 66a of the light-shielding film 66.

In the present embodiment, the signal electric charges produced from the incident light component of the short 10 wavelength B and that of the long wavelength R, which are spaced away from each other, are stored in the respective storage layers 62, 63. The storage layers 62, 63 can be formed at positions spaced apart from each other in the depthwise direction of the semiconductor substrate. The storage layers 62, 63 are readily 15 formed separately.

As in the case of the first and second embodiments, the P<sup>+</sup> layer 15 and the SiO<sub>2</sub> film 16 are provided on the top surface of the semiconductor substrate 60.

In Fig. 20B, a signal electric charge storage layer (n2) 20 64 (color signal detecting layer) formed from an N<sup>+</sup> layer of single-layer structure is formed at a surface section within the P well layer 61 formed at a position close to the surface side of the n-type semiconductor substrate 60. The depth of the storage layer 64 is an intermediate depth between the depth 25 of the storage layer 62 and that of the storage layer 63, both

being shown in Fig. 20A.

The end section of the storage layer 64 extends up to a position below the read gate electrodes 56a, 57a formed from portions of the transfer electrodes 56, 57. The signal electric 5 charges primarily produced from an incident light component of intermediate wavelength (e.g., G) are stored in the end section of the storage layer 64. In this structure, only the electric charges stored in the storage layer 64; that is, the electric charges produced primarily from light of intermediate 10 wavelength, are read to the vertical transfer path 52 through two operations.

A light-shielding film 66 having openings 66b is also placed on top of the light-receiving section in which the storage layer 64 of such a configuration is formed. A G filter 65 and 15 a microlens 69 are stacked on the light-shielding film 66. Light is gathered by the microlens 69, and the incident light—for which light of a red (R) wavelength and light of a blue (B) wavelength are blocked by the G filter 41—enters the light-receiving section by way of the opening 66b of the 20 light-shielding film 66.

In contrast with the first and second embodiments, the color solid-state image pickup device of the embodiment has one or two storage layers in the depthwise direction of the substrate. The storage layers n1(62), n2(64), and n3(63) are 25 arranged in the sequence of increasing sequence. Depths of

the storage layers are set in the sequence of increasing depth such that B light signal electric charges, G light signal electric charges, and R light signal electric charges are stored.

The storage layer (n2) 64 is distributed up to the vicinity 5 of the surface of the substrate. However, the G filter is stacked on the storage layer, and hence the B signal does not reach the storage layer 64. Therefore, the storage layer does not have any sensitivity to B. Accordingly, no particular problem of a color mixture or the like arises.

10 As in the case of the first and second embodiments, the electric charges of the respective storage layers can be read to the vertical transfer path independently. Specifically, single ends of the respective storage layers located in the  $N^+$  region extend up to the neighborhood of different read gate 15 sections. The electric charges stored in the storage layers can be read to the vertical transfer path by application of a read pulse ( $\Phi_v$ ).

In the embodiment, the G signal is read from the same storage layer 64 through two reading operations. However, all 20 the stored electric charges may be read from the storage layer 64 by the first reading operation.

Figs. 21A, 21B are conceptual renderings for describing the solid-state image pickup device of the embodiment, wherein the light signals having passed through the Mg filter 67 and 25 the G filter 65 travel over different distances in the silicon

substrate in the depthwise direction thereof for reasons of the wavelengths of the light signals.

The B light, which is of the shortest wavelength, is absorbed at the most shallow region of the silicon substrate, 5 thereby producing electric charges. The thus-produced electric charges are stored in the first storage layer n1. The G light, formed from an intermediate wavelength, reaches the position which is deeper than that achieved by the light B. Hence, the majority of the produced electric charges is stored 10 in the storage layer n2. Similarly, the electric charges produced by the R light of the longest wavelength are stored in the storage layer n3 located at the deepest location of the silicon substrate.

Fig. 22 is a plot showing that a spectral sensitivity 15 spectrum of the G signal output from the light-receiving section having the green filter stacked thereon is superimposed on spectral sensitivity spectra of the B and R signals output from the light-receiving sections having the magenta filter of the embodiment stacked thereon.

20 In the solid-state image pickup device using the filters of complementary color system and the green filter, the green filter is embodied by superimposing two color filters; that is, a cyan filter and a yellow filter, one on top of the other for manufacturing reasons. Because, use of a plurality of kinds 25 of color filters is not usually desired. Therefore, the

spectrum of the green signal produced by such filters fails to be ideal.

However, since the filter of complementary color system of the embodiment is only magenta, there is no necessity for 5 superimposing cyan and yellow filters one on top of the other in order to implement a green filter. Only one green filter of primary color system can be provided. Further, the magenta filter permits passage of the B and R signals whose wavelengths are separated from each other. Hence, as shown in Fig. 22, 10 the spectral sensitivity spectra of the R, G, and B signals obtained in the embodiment become close to the ideal spectral sensitivity spectra which involves a smaller overlap and effects superior color separation. Therefore, color reproduction more faithful than that achieved in the first and second embodiments 15 can be realized by means of subjecting the color signals produced by the solid-state image pickup device of the embodiment to image processing.

As mentioned above, even in the present embodiment, an attempt can be made to enhance sensitivity by means of increasing 20 the utilization factor of incident light through use of the Mg filter from among the filters of complementary color system. Moreover, each light-receiving section can directly read the primary color signal by means of making a distinction between color signals. A necessity for color signal separation 25 processing operation is obviates, thereby enabling faithful

reproduction of colors and rendering image quality high.

Although the present embodiment has described the solid-state image pickup device having the light-receiving sections 21 arranged in a square grid pattern, the present 5 embodiment can also be applied to a solid-state image pickup having the light-receiving sections 21 arranged in a so-called honeycomb pattern.

(Fourth Embodiment)

Fig. 23 is a schematic surface view of a CCD color 10 solid-state image pickup device of single plate type according to a fourth embodiment of the invention. In this CCD color solid-state image pickup device, a plurality of light-receiving sections 71 are formed in the form of an array on the surface of a semiconductor substrate 80. In an illustrate embodiment, 15 each light-receiving section 71 is represented by a rhombus.

The arrangement of pixels of the present embodiment is identical with that described in connection with the first embodiment; that is, a so-called honeycomb pixel arrangement formed by offsetting the light-receiving sections 71 by half 20 pitches in both the vertical and horizontal directions. A vertical transfer path 72 (signal reading unit) is formed between adjacent light-receiving sections 71, and signal electric charges read from the respective light-receiving sections 71 to the vertical transfer path 72 are transferred in a meandering 25 manner to a horizontal transfer path 73 located at a downward

position.

In the embodiment, Mg filters are stacked on the respective light-receiving sections 71 provided in even columns, and instead of the color filters, mere transparent planarized films 5 (also called "white filters") are stacked on the respective light-receiving sections 71 provided in odd columns. R signal electric charges formed from incident light components R which are not blocked by the Mg filter and B signal electric charges formed from incident light components B which are not blocked 10 by the Mg filter are stored in a distinguished manner in the light-receiving sections 71 with the Mg filter stacked thereon. The R, B signal electric charges are read independently, and the light-receiving sections 71 having the W filter stacked thereon have sensitivity to all visible rays.

15 Specifically, the light-receiving sections having the Mg filters output R and B signals, and signals output from the light-receiving sections having the W filters are formed by adding all the R, G, and B signal components. W1 and W2 signals output by two reading operations are added together and used 20 as the W signals to be output from the light-receiving sections having the W filters.

Consequently, as a result of two operations for reading electric charges from the respective light-receiving sections and transferring the electric charges over the VCCD and HCCD, 25 the light-receiving sections having the Mg filters stacked

thereon output two primary color signal components R, B in such a manner as shown in Fig. 24. The light-receiving sections having the W filters stacked thereon output (R+G+B) signals formed by mixing R, G, and B.

5 Specifically, the magnitude of the R signal and that of the B signal are subtracted from the two primary color signals R, B, and a mean value (R+G+B) of four or eight peripheral W signals, thereby determining the G signal as color information pertaining to the location of the light-receiving section having  
10 the Mg filter.

The R signal is determined from a mean value of four peripheral R signals as color information pertaining the position of the light-receiving section having the W filter. The B signal is determined from a mean value of four peripheral B signals. The G signal is determined by subtracting the magnitude of the R signal and that of the B signal from the magnitude of the directly-obtained W signal.

Fig. 25 is a plan view showing a pattern of four pixels of the light-receiving section 71 shown in Fig. 23 and a pattern 20 of the vertical transfer path 72 laid between the light-receiving sections 71. The light-receiving sections 71 are partitioned from each other by means of rhombus element isolation regions 74. Of four sides of the rhombus, gate sections 74a, 74b are formed in two right sides where the element isolation region 25 74 is broken. When the B signal is read from the light-receiving

section 71 having the Mg filter, the signal is read from the gate section 74a. When the R signal is read, the signal is read from the gate section 74b. The first W signal is read from the light-receiving section 71 having the W filter, by 5 way of the gate section 74a. A second W signal is read by way of the gate section 74b. All the W signals of the light-receiving section 71 may be read by one W signal reading operation.

The transfer electrode structure provided on the vertical transfer path 72 is the same as that employed in the first 10 embodiment; that is, two-layer polysilicon.

Fig. 26A is a cross-sectional view of the light-receiving section having a W filter taken along line a-a shown in Fig. 25. A P well layer 81 is formed on the surface of an n-type semiconductor substrate 80. A signal electric charge storage 15 layer (n2) 82 (color signal detecting layer) which is as deep as 0.2 to 2.5  $\mu\text{m}$  and formed from an N<sup>+</sup> layer is formed in the surface of the P well layer 81. As in the case of the first through third embodiments, the P<sup>+</sup> layer 15 and the SiO<sub>2</sub> film 16 are provided on the top surface of the light receiving section. 20 An opening 85a of a light-shielding film 85 is provided on a light-receiving surface of the light-receiving section. A transparent planarized film 86; that is, a W filter, is provided on the opening 85a. Further, a microlens 87 is provided at a position above the planarized film 86. The incident light 25 gathered by the microlens 87 passes through the transparent

planarized film 86, thereby entering the storage layer 82 with a small loss.

Fig. 26B is a cross-sectional view taken along line b-b shown in Fig. 25; that is, a cross-sectional view of a 5 light-receiving section having a Mg filter. Signal electric charge storage layers 83, 84 (color signal detecting layers), both being formed from an  $N^+$  layer of two-layer structure, are formed separately in the P well layer 81 formed on the n-type semiconductor substrate 80. As mentioned above, the  $P^+$  layer 10 15 and the  $SiO_2$  film 16 are formed on top of the light-receiving section.

The storage layer (n1) 83 provided at the surface section extends up to a position below the read gate electrode formed from a portion of the transfer electrode. Signal electric 15 charges formed primarily from incident light components of short wavelength light (e.g., B) are stored in the storage layer 83 provided at the position most shallow with respect to the thicknesswise direction of the semiconductor substrate 80. In this structure, the electric charges stored in the storage layer 20 83; that is, only the electric charges produced primarily from light of short wavelength, are read to the vertical transfer path 72.

The storage layer (n3) 84 formed at a deep location has, at an end section thereof, an  $N^+$  region (i.e., a charge path) 25 84a which extends up to the surface of the semiconductor

substrate 80. This  $N^+$  region 84a extends up to a position below the read gate electrode formed from a portion of the transfer electrode. The signal electric charges formed from light of long wavelength (e.g., R) are stored in the storage layer 84.

5 In this structure, the electric charges stored in the storage layer 84; that is, electric charges produced primarily from the light (R) of long wavelength, are read to the vertical transfer path 72.

An opening 85b of a light-shielding film 85 is provided 10 on the light-receiving section having the storage layers 83, 84 of such a structure in alignment with the light-receiving surface of the light-receiving section. Moreover, a Mg filter 88 and a microlens 89 are stacked on the openings 85b, and the microlens 89 gathers light. The incident light whose green 15 (G) wavelength light is blocked by the Mg filter 88 enters the light-receiving section by way of the opening section 85b of the light-shielding film 85.

In relation to the storage layers n1(83), n2(82), and 20 n3(84), the storage layer n1 is the most shallow, and the storage layers n2, n3 are located at essentially the same depth. The storage layer n3 is localized at a spaced location so as not to contact the storage layer n1 located above the storage layer n3. In short, the storage layer n3 is selectively set to a depth such that the highest sensitivity is achieved by the 25 wavelength component of R light. The storage layer n2 is

distributed up to the neighborhood of the surface and to the same depth as that of the storage layer n3. The reason for this is that the incident light wavelength components in a visible range which can be perceived by the human eye are 5 subjected to photoelectric conversion most efficiently and that the colorless (W) filter is stacked on the light-receiving section.

Figs. 27A and 27B are conceptual renderings for describing a difference in distances over which the light signals having 10 passed through the Mg and W filters travel in the depthwise direction of the silicon substrate for reasons of their wavelengths. Specifically, the B light, which is of shortest wavelength, is absorbed by the most shallow region of the silicon substrate, thereby producing electric charges. The 15 thus-produced electric charges are stored in the first storage layer n1. Similarly, the electric charges produced by the R light, which is of longest wavelength, are stored in the storage layer n3 located at the deepest position in the silicon substrate. The light-receiving sections, each having the W filter 86, must 20 subject all the R, G, and B light beams to photoelectric conversion. Hence, the storage layer n2 is distributed widely from a shallow portion to a deep portion of the substrate.

Fig. 28 is a view showing a spectral sensitivity spectrum of the color solid-state image pickup device of the embodiment. 25 The B and R signals having passed through the magenta Mg filter

are separated from each other without an overlap. The signal (W) of light (B+G+R) having passed through the W filter includes all visible light wavelength ranges and assumes a spectrum whose peak appears at the wavelength of the G signal (i.e., the 5 neighborhood of a wavelength of 540 nm).

In the embodiment, particularly the light-receiving sections assigned the white (W) filters can utilize wavelength components of all visible ranges, and hence no substantial loss arises in the incident light component. When compared with 10 a case where the complementary color filters are stacked on all the light-receiving sections as in the first case, an attempt can be made to enhance sensitivity to a much greater extent. Moreover, the present embodiment is also characterized in that 15 a high-sensitivity luminance signal (R+G+B) is obtained directly without involvement of any particularly complicate signal processing operation. Since only the Mg filter is used as a color filter, a process for stacking color filters becomes easy.

The present embodiment has described a solid-state image 20 pickup device having the respective light-receiving sections 71 arranged in a so-called honeycomb pattern. However, the present embodiment can also be applied to a solid-state image pickup device having the light-receiving sections 71 arranged in a square grid pattern.

25 (Fifth Embodiment)

Fig. 29 is a schematic surface view of a CCD color solid-state image pickup device according to a fifth embodiment of the invention. The present embodiment differs from the second embodiment only in that a green (G) filter, a magenta (Mg) filter, a yellow (Ye) filter, and a cyan (Cy) filter are stacked on respective light-receiving sections 91 arranged on a semiconductor substrate 90 in a square grid pattern. Color signal electric charges read from the respective light-receiving sections 91 to a vertical transfer path 92 (signal reading unit) are transferred to a horizontal transfer path 93. The cross-sectional structure of each light-receiving section 91 is the same as that of the light-receiving section on which the same color filter as that employed in the previous embodiment is stacked.

The only difference of the solid-state image pickup device of the embodiment lies in color filters to be stacked on the respective light-receiving sections. In relation to a color difference line sequential signal output from a CCD, by means of arrangement of the color filter of the embodiment, signals of "n" ("n" is an integer of 1 or more) lines are formed from green (G), yellow (Ye), cyan (Cy), and magenta (Mg), and a signal of  $n+1$  lines is formed from magenta (Mg), yellow (Ye), cyan (Cy), and green (G). These signals are repeated.

Therefore, even when interlace reading (interlaced scanning) is performed, according to the embodiment R, G, and

B color components are read independently. Hence, a color separation circuit is not required. Therefore, photographing of a high-quality image with low noise and superior color reproducibility becomes feasible, and an attempt can be made  
5 to simplify high-speed signal processing and a signal processing circuit.

(Sixth Embodiment)

Fig. 30 is a schematic surface view of a CMOS color solid-state image pickup device according to a sixth embodiment 10 of the invention. This CMOS color solid-state image pickup device is fabricated on the surface of an n-type semiconductor substrate 110 and comprises a light-receiving area 111; a vertical scanning circuit 112 formed beside the light-receiving area 111; and a horizontal scanning circuit or the like (e.g., 15 a signal amplifier circuit, an analog-to-digital conversion circuit, a synchronous signal generation circuit, or the like) 113 formed at a position close to the bottom side of the semiconductor substrate 110.

In this embodiment, a plurality of light-receiving 20 sections, which will be described later, are arranged and formed in a two-dimensional array or a square grid pattern within the light-receiving area 111, and mono color filters are stacked on top of the respective light-receiving sections. Color filters of a complementary color system; that is, cyan (Cy), 25 yellow (Ye), magenta (Mg), and green (G) color filters, are

used as the color filters. The G filters and the Mg filters are alternately arranged in odd rows, and the Ye filter and the Cy filter are alternately arranged in even rows. This color filter arrangement is generally called a color difference 5 sequential arrangement. The arrangement can also be embodied by combination of three color filters Ye, Cy, and Mg which do not include the G filters. The case of four color filters will now be described.

Fig. 31A is a cross-sectional block diagram taken along 10 line XXXIa-XXXIa shown in Fig. 30, i.e., a cross-sectional block diagram of a light-receiving section with a Cy filter 151 stacked thereon; and Fig. 31B is a cross-sectional block diagram taken along line XXXIb-XXXIb shown in Fig. 30, i.e., a cross-sectional block diagram of a light-receiving section with an Mg filter 152 stacked thereon. Similarly, Fig. 32A is a cross-sectional 15 block diagram taken along line XXXIIa-XXXIIa shown in Fig. 30, i.e., a cross-sectional block diagram of a light-receiving section with a Ye filter 153 stacked thereon; and Fig. 32B is a cross-sectional block diagram taken along line XXXIIB-XXXIIB 20 shown in Fig. 30, i.e., a cross-sectional block diagram of a light-receiving section with a G filter 154 stacked thereon.

As shown in Fig. 31A, the light-receiving section with the Cy (cyan) filter 151 stacked thereon blocks only a red (R) light component of the incident light, whereupon B (blue) and 25 G (green) light components reach the light-receiving section.

In this light-receiving section, a P well layer 115 is formed on the surface of an n-type semiconductor substrate 110, and an N<sup>+</sup> layer (n1) 116 (color signal detecting layer) having a depth of 0.1 to 0.3  $\mu\text{m}$  is formed in the surface within the P well layer 115. An N<sup>+</sup> layer (n2) 117 (color signal detecting layer) having a depth of 0.3 to 0.8  $\mu\text{m}$  is formed at a slightly deep position within the P well layer 115 so as to be separated from the N<sup>+</sup> layer 116. An electric charge path 117a extending up to the surface of the light-receiving section is provided at an end section of the N<sup>+</sup> layer 117.

In this embodiment, dopant [phosphorous or arsenic (P or As)] content of the N<sup>+</sup> layers 116, 117, and 117a is set to about  $5 \times 10^{16-17}/\text{cm}^3$ . The depths of the N<sup>+</sup> layers 116, 117 are also dependent on this dopant content.

A P region which is to act as a potential barrier is interposed between the N<sup>+</sup> layers 116, 117. The P region is maintained at the same potential as that of the P well layer 115. In order to change the thickness of the potential barrier, the dopant (boron) content ( $1 \times 10^{15-16}/\text{cm}^3$ ) of the P region existing between the N<sup>+</sup> layers 116, 117 may be set so as to differ from that ( $7 \times 10^{14-15}/\text{cm}^3$ ) of the P well layer 115.

The N<sup>+</sup> layer 116 is connected to a B signal detection amplifier 122 by way of an ohmic contact 121. The electric charge path 117a of the N<sup>+</sup> layer 117 is connected to a G signal detection amplifier 124 by way of an ohmic contact 123. In

order to establish the superior ohmic contacts 121, 123, the dopant content of contact portions of the N<sup>+</sup> layers 116, 117a is set to  $1 \times 10^{19}/\text{cm}^3$  or higher.

By means of the cross-sectional structure of this 5 light-receiving section, a reset transistor is activated before photographing a color image. A predetermined amount of electric charges are stored in PN junction sections of the respective N<sup>+</sup> layers 116, 117. The electric charges stored in the PN junction section of the N<sup>+</sup> layer 116 are discharged by an amount 10 corresponding to the photocarriers produced in correspondence to the quantity of B (blue) incident light of the incident light arrived at the light-receiving section. The electric charges stored in the PN junction section of the N<sup>+</sup> layer 117 are discharged by an amount corresponding to the photocarriers 15 produced in correspondence to the quantity of G (green) incident light. The amount of changes in the electric charges stored in the respective PN junctions of the respective N<sup>+</sup> layers 116, 117 are independently read by amplifiers 122, 124 as B and C signals.

20 As shown in Fig. 31B, the light-receiving section with the Mg (magenta) filter 152 stacked thereon blocks only a green (G) light component of the incident light, whereupon B (blue) and R (red) light components reach the light-receiving section. In this light-receiving section, the N<sup>+</sup> layer (n1) 116 that 25 is the same as that described by reference to Fig. 31A is formed

in the P well layer 115 formed in the surface of the n-type semiconductor substrate 110. An N<sup>+</sup> layer (n3) 118 (color signal detecting layer) having a depth of 0.8 to 2.5  $\mu\text{m}$  is formed at a deeper position within the P well layer 115 so as to be separated 5 from the N<sup>+</sup> layer 116. An electric charge path 118a extending up to the surface of the light-receiving section is provided at an end section of the N<sup>+</sup> layer 118.

The N<sup>+</sup> layer 116 is connected to the amplifier 122 by way of the ohmic contact 121. The electric charge path 118a 10 is connected to an R signal detection amplifier 126 by way of an ohmic contact 125. The dopant content of the P region located between the N<sup>+</sup> layers 116, 118 may be set so as to differ from that of the P well layer 115 in the same manner as that described by reference to Fig. 31A. The dopant content of the N<sup>+</sup> layers 15 116, 118, and 118a and the dopant content of the ohmic contact sections are the same as those described by reference to Fig. 31A. The dopant content also applies to the following descriptions.

By means of the cross-sectional structure of this 20 light-receiving section, the reset transistor is activated before photographing a color image, whereby a predetermined amount of electric charges are stored in PN junction sections of the respective N<sup>+</sup> layers 116, 118. The electric charges stored in the PN junction section of the N<sup>+</sup> layer 116 are 25 discharged by an amount corresponding to the photocarriers

produced in correspondence to the quantity of B (blue) incident light of the incident light having arrived at the light-receiving section. The electric charges stored in the PN junction section of the  $N^+$  layer 118 are discharged by an amount corresponding 5 to the photocarriers produced in correspondence to the quantity of R (red) incident light. The amounts of changes in the electric charges are independently read by amplifiers 122, 126 as B and R signals.

As shown in Fig. 32A, the light-receiving section with 10 the  $Y_e$  (yellow) filter 153 stacked thereon blocks only the B (blue) light component of the incident light, whereupon the G (green) and R (red) light components arrive at the light-receiving section. In this light-receiving section, the  $N^+$  layer (n3) 118 that is the same as that described by reference 15 to Fig. 31B is formed within the P well layer 115 formed on the surface of the n-type semiconductor substrate 110. An  $N^+$  layer (n2') 119 (color signal detecting layer) having a depth of 0.1 to 0.8  $\mu m$  is formed in the surface so as to be separated from the  $N^+$  layer 118. A G signal detection amplifier 128 is 20 connected to the  $N^+$  layer 119 by way of an ohmic contact 127.

By means of the cross-sectional structure of this light-receiving section, the reset transistor is activated before photographing a color image, whereby a predetermined amount of electric charges are stored in PN junction sections 25 of the respective  $N^+$  layers 118, 119. The electric charges

stored in the  $N^+$  layer 119 are discharged by an amount corresponding to the photocarriers produced in correspondence to the quantity of G (green) incident light of the incident light having arrived at the light-receiving section. The 5 electric charges stored in the  $N^+$  layer 118 are discharged by an amount corresponding to the photocarriers produced in correspondence to the quantity of R (red) incident light. Changes in the amounts of electric charges of the respective  $N^+$  layers 118, 119 are independently read by amplifiers 126, 10 128 as R and G signals.

In the embodiment, the  $N^+$  layer 119 for detecting a G signal is set to a depth of 0.1 to 0.8  $\mu\text{m}$ . However, as in the case of the  $N^+$  layer 117 shown in Fig. 31A, the  $N^+$  layer 119 may be formed to a depth ranging from 0.3 to 0.8  $\mu\text{m}$ . However, 15 even in the case of the structure of the  $N^+$  layer 119, B (blue) light of the incident light is blocked by the Ye filter. Hence, a change in the amount of electric charges corresponding to the amount of incident light G (green) arises in the  $N^+$  layer 119, and hence mixing of B and G colors does not arise.

20 As shown in Fig. 32B, the light-receiving section with the G (green) filter 154 stacked thereon permits transmission of only the G (green) light component of the incident light, thereby blocking the B (blue) and R (red) light components from arriving at the light-receiving section. In this 25 light-receiving section, the  $N^+$  layer ( $n2'$ ) 119 having the same

depth as that described by reference to Fig. 32A; that is, a depth of 0.1 to 0.8  $\mu\text{m}$ , is formed in the surface of the P well layer 115 formed on the n-type semiconductor substrate 110. The amplifier 128 for detecting a G signal is connected to the 5  $\text{N}^+$  layer 119 by means of the ohmic contact 127.

By means of the cross-sectional structure of such a light-receiving section, the reset transistor is activated before photographing a color image, whereupon a predetermined amount of electric charges are stored in the PN junctions of 10 the respective  $\text{N}^+$  layers 119. The thus-stored electric charges are discharged by an amount corresponding to the photocarriers produced in correspondence to the quantity of G (green) incident light of the incident light having passed through the G filter. A signal corresponding to the amount of change in electric 15 charges is read as a G signal by the amplifier 128.

Since the light-receiving section reads only the G signal, only one channel consisting of an ohmic contact and peripheral circuits is needed to be provided for the  $\text{N}^+$  layer 119. Thus, the configuration of the light-receiving section is simplified. 20 The G filter may be formed as a primary color filter. Alternatively, the G filter may be imparted with a filtering characteristic of permitting transmission of only G light superimposing the yellow filter and the cyan filter, both being filters of a complementary color system, one on top of the other. 25 The configurations of the amplifiers 122, 124, 126, and

128 include the equivalent circuits shown in Fig. 33. Although omitted from Figs. 31 and 32, the topmost surface of the semiconductor substrate other than those occupied by the contact sections is covered with a protective  $\text{SiO}_2$  film.

5 Figs. 34A, 34B and Figs. 35A, 35B are views showing the relationship between the potential profile of the light-receiving sections of the color solid-state image pickup device of the embodiment—the Cy filter, the Mg filter, the Ye filter, and the G filter are stacked on the light-receiving 10 sections—in the depthwise direction of the substrate and the depth to which incident light enters. In contrast with the related-art CMOS sensor, the light-receiving section of the embodiment with the filters of a complementary color system stacked thereon is characterized by comprising two-stages; that 15 is, an  $\text{N}^+$  region and a P region interposed between the  $\text{N}^+$  regions, in the depthwise direction of the substrate. The depths of the respective  $\text{N}^+$  regions ( $n_1$ ,  $n_2$ , and  $n_3$ ) change dependent on the stacked filters of a complementary color system.

Specifically, signals of incident light wavelengths which 20 have not been blocked by the filters of a complementary color system and subjected to photoelectric conversion must be read independently. The depths of the impurity layers are determined such that the incident light is subjected to photoelectric conversion most efficiently, whereby a read circuit is connected. 25 The B light having the shortest wavelength is absorbed by the

most shallow area of the silicon substrate. Hence, photocarriers are produced in the vicinity of the n1 layer ( $N^+$  layer 116). The G light formed from an intermediate wavelength reaches a position deeper than that achieved by the B light.

5 Hence, photocarriers are induced in the vicinity of the n2 layer ( $N^+$  layer 117) located at an intermediate depth. Similarly, photocarriers are produced by the R light having the shortest wavelength in the vicinity of the n3 layer ( $N^+$  layer 118) located at the deepest location of the silicon substrate.

10 In the case of the G light, the B light is blocked by the G filter or the Ye filter. Hence, there is no necessity for dividing the N layer into the n1 layer and the n2 layer. There is set an  $N^+$  region 119 which is substantially identical in depth with the n2 layer and indicated by n2' layer. In this 15 embodiment, the n1 layer, the n2 layer (n2' layer), and the n3 layer are set in an increasing sequence of depth. The depths of the respective  $N^+$  layers are set for such that the photoelectric conversion efficiency of the B light, that of the G light, and that of the R light become highest.

20 Figs. 36A, 36B and Figs. 37A, 37B are views showing spectral sensitivity spectra of signals obtained by the light-receiving sections with the Cy filter, the Mg filter, the Ye filter, and the G filter stacked thereon. The horizontal axis shows the wavelength of incident light (nm), and the vertical axis shows 25 relative sensitivity (%) of the output signal.

In each light-receiving section, the wavelength dependence of the output signal is dominated by the spectral transmission factor of the stacked color filter. In the light-receiving section of the color solid-state image pickup device of the embodiment, in which the filter of a complementary color system is stacked on the light-receiving section, there exists a P region, which is to act as a potential barrier existing between the N<sup>+</sup> layers; that is, a P region sandwiched between the N<sup>+</sup> layers. Signal charges (i.e., electrons) having developed in the P region are allocated to any of the adjacent N<sup>+</sup> layers by means of the potential barrier, thereby yielding an advantage of a small overlap existing between spectra.

When compared with a case where electric charges (positive holes) developed in the P region are read directly from the surface of the P region as in the case of the related-art CMOS color solid-state image pickup device described in USP No. 5965875, the color solid-state image pickup device of the embodiment yields an advantage of an increase in the performance for separating color signals attributable to use of only signals output from only the two N<sup>+</sup> layers.

In the light-receiving section with the cyan (Cy) filter stacked thereon, the majority of light of a wavelength corresponding to R is blocked by the Cy filter. Hence, the wavelength dependence of a signal output from the light-receiving section is sharply attenuated in this

wavelength range. Accordingly, the B output signal and the G output signal are understood to be unaffected by the light of the R wavelength.

In the light-receiving section with the magenta (Mg) filter stacked thereon, the majority of light of a wavelength corresponding to G is blocked by the Mg filter. Hence, the wavelength dependence of a signal output from the light-receiving section is sharply attenuated in this wavelength range. Accordingly, the B output signal and the R output signal exhibit spectra having no essential overlaps therebetween.

In the light-receiving section with the yellow (Ye) filter stacked thereon, the majority of light of a wavelength corresponding to B is blocked by the Ye filter. Hence, the wavelength dependence of a signal output from the light-receiving section is sharply attenuated in this wavelength range. Accordingly, the G output signal and the R output signal are understood to be unaffected by the light of the B wavelength.

In the light-receiving section with the green (G) filter stacked thereon, the majority of light of wavelengths corresponding to B and R is blocked by the G filter. Hence, the wavelength dependence of a signal output from the light-receiving section is sharply attenuated in this wavelength range. Accordingly, the G output signal is

understood to be unaffected by the light of B and R wavelengths and exhibit an ideal spectral characteristic.

Specifically, the light-receiving section with the Cy filter stacked thereon outputs the separated B and G signals 5 involving a little color mixture; the light-receiving section with the Mg filter stacked thereon outputs the separated B and R signals involving a little color mixture; the light-receiving section with the Ye filter stacked thereon outputs the separated G and R signals involving a little color mixture; and the 10 light-receiving section with the G filter stacked thereon outputs only the G signal.

Fig. 38 is a descriptive view for reproducing color information by acquisition of signals of three colors, R, G and B at the positions of the light-receiving sections. As 15 mentioned previously, each light-receiving section of the embodiment is configured to read signals of two primary colors or a signal of one primary color directly from one light-receiving section. Specifically, the R signal component and the B signal component are deficient at the position of 20 the light-receiving section with the G filter stacked thereon. The B signal component is deficient at the position of the light-receiving section with the Ye filter stacked thereon. The R signal component is deficient at the position of the light-receiving section with the Cy filter stacked thereon. 25 The G signal component is deficient at the position of the

light-receiving section with the Mg filter stacked thereon.

Therefore, as shown in Fig. 38, the color solid-state image pickup device of the embodiment determines the deficient signal component by subjecting signal components obtained by 5 adjacent light-receiving sections to interpolation processing. A mean value determined by means of adding together four R signal components produced by the light-receiving sections—which are vertically and horizontally adjacent to the light-receiving section of interest—is used as the R signal component deficient 10 at the position of the light-receiving section with the Cy filter stacked thereon.

Similarly, a mean value determined by means of adding together four G signal components produced by the light-receiving sections—which are vertically and 15 horizontally adjacent to the light-receiving section of interest—is used as the G signal component deficient at the position of the light-receiving section with the Mg filter stacked thereon. A mean value determined by means of adding together B signal components produced by the light-receiving 20 sections—which are horizontally or diagonally adjacent to the light-receiving section of interest—and averaging the resultant sum is used as the B signal component deficient at the position of the light-receiving section with the Ye filter stacked thereon. A mean value determined by means of adding 25 together R signal components output from light-receiving

sections vertically, horizontally, or diagonally adjacent to the light-receiving section of interest and averaging the resultant sum and a mean value determined by means of adding together B signal components output from light-receiving

5 sections vertically, horizontally, or diagonally adjacent to the light-receiving section of interest and averaging the resultant sum are used as an R signal component and a B signal component, which are deficient at the position of the light-receiving section with the G filter stacked thereon.

10 The three primary color signals R, G, and B obtained in this manner at the positions of the respective light-receiving sections are processed by an external color signal processing circuit, whereby the color solid-state image pickup device of the embodiment can reproduce colors faithfully.

15 Fig. 39 is a two-dimensional plan view of four pixels of the color solid-state image pickup device of the embodiment (Mg, Cy, Ye, and G). The respective light-receiving sections on the surface of the semiconductor substrate are isolated from each other in a lattice pattern by means of element isolation 20 regions 30 which extends in a crisscrossing manner and is formed by LOCOS processes. In the illustrated embodiment, each light-receiving section assumes the shape of an essential square.

The N<sup>+</sup> layers 116, 117, 118, and 119 are formed in the 25 majority of areas of the light-receiving sections. A

strip-shaped peripheral circuit 131 is provided on the right end of each of the light-receiving sections with the Mg, Ye, and Cy filters of a complementary color system stacked thereon. A peripheral circuit section 131' is provided at only an upper 5 portion of the right end of the light-receiving section with the filter G of a primary color system stacked thereon. The peripheral circuit sections 131, 131' are provided with the previously-described amplifiers (source follower amplifiers) 122 to 128. Color signals are read from the  $N^+$  layers connected 10 to the amplifiers via the contact holes 137 formed in the respective light-receiving sections.

In the drawing, a signal output line 133 (signal reading unit), a power line 134, and a reset line 135 are laid on the element isolation regions 130 provided in the vertical direction. 15 Select signal lines 136 are laid on the element isolation regions 130 provided the horizontal direction. The signal output lines 133 are connected to output terminals of the respective amplifiers 122 to 128. A source voltage is applied to the power line 134, and a reset signal is applied to the reset line 133. 20 The select signal and the reset signal are controlled by the vertical scanning circuit 112 and the horizontal scanning circuit 113 shown in Fig. 30. A rectangular frame 138 which is provided in each light-receiving section and denoted by dotted lines indicates the position of an opening section of the 25 light-shielding film. Light passes through only the inside

of the frame, thereby shielding, from light, the peripheral circuit sections 131, 131' and the contact hole 137 located outside the frame. As illustrated, the number of signal lines and peripheral circuits which must be provided in one

5 light-receiving section becomes smaller than that required by the related-art color solid-state image pickup device. Hence, the color solid-state image pickup device of the embodiment enables broadening of the area of the light-receiving sections, thereby enabling photographing a bright image.

10 Figs. 40A, 40B are cross-sectional views prepared by adding, to the cross-sectional schematic views shown in Figs. 31A, 31B, a microlens 140, a light-shielding film 141, a contact section 142 having the contact hole 137, and a metal wiring layer 143 to be connected to the contact section 142. Figs.

15 41A, 41B are cross-sectional views prepared by adding, to the cross-sectional schematic views shown in Figs. 32A, 32B, the microlens 140, the light-shielding film 141, the contact section 142 having the contact hole 137, and the metal wiring layer 143 to be connected to the contact section 142.

20 The microlenses 140 are formed on the respective color filters 151, 152, 153, and 154 via the transparent planarized film 145. A transparent planarized film layer 146 is provided between the color filters 151 to 154 and the light-shielding film 141. The transparent planarized film layer 146 also acts  
25 as a signal line layer and is provided in a so-called triple-layer

structure such that the signal lines 133, 134, 135, and 136 do not come into contact with each other via the interlayer dielectric film (not shown).

The opening section 138 of the light-shielding film 141 is located at substantially the center of the PN junction region serving as a photoelectric conversion section. Peripheral circuit sections, such as the amplifiers 122 to 128, are arranged below the light-shielding film 141. The depth of the most shallow N<sup>+</sup> layer 116 is made greater only at the position below 10 the contact section 142. The reason for this is to prevent rupture of the PN junction, which would otherwise be caused by penetration of metal or formation of an alloy between the metal electrode of the contact section 142 and silicon of the substrate. Since this portion is shielded by the 15 light-shielding film 141, no influence is exerted on the wavelength dependence (a spectral characteristic) of the photoelectric conversion characteristic.

(Seventh Embodiment)

Fig. 42 is a schematic surface view of a CMOS color 20 solid-state image pickup of single plate type according to a seventh embodiment of the invention. A difference between the sixth and seventh embodiments lies only in the arrangement of filters of a complementary color system to be stacked on the light-receiving sections. Only the cyan (Cy) filter and the 25 yellow (Ye) filters are used in this embodiment, and the Cy

and Ye filters are alternately arranged in both vertical and horizontal directions.

The cross-sectional structure of the light-receiving section with the Cy filter stacked thereon is identical with that shown in Fig. 31A (or Fig. 40A). The potential profile of the light-receiving section is identical with that shown in Fig. 34A, and the spectrum of the light-receiving section is identical with that shown in Fig. 36A. Of the incident light, the B signal component and the G signal component are output from the light-receiving section with the Cy filter stacked thereon.

The cross section of the light-receiving section with the Ye filter stacked thereon is identical with that shown in Fig. 32A (or Fig. 41A). Further, the potential profile of the light-receiving section is identical with that shown in Fig. 35A, and the spectrum of the light-receiving section is identical with that shown in Fig. 37A. More specifically, of the incident light, the G signal component and the R signal component are output from the light-receiving section with the Ye filter stacked thereon.

Accordingly, in the CMOS color solid-state image pickup device of the embodiment, all the light-receiving sections output the G signal component. The R signal component becomes deficient at the position of the light-receiving section with the Cy filter stacked thereon. The B signal component becomes

deficient at the position of the light-receiving section with the Ye filter stacked thereon.

Reading of a color signal from each light-receiving section is performed twice, and primary color components of 5 two colors are independently obtained from one light-receiving section. Subsequently, as shown in Fig. 43, one deficient signal component is determined by means of adding together four signal components output from vertically and horizontally adjacent four light-receiving components and averaging the 10 resultant sum. As a result, faithful color reproduction can be performed by means of an external color signal processing circuit.

Fig. 44 is analogous to Fig. 39; that is, a two-dimensional plan view corresponding to four pixels (Ye x 2, Cy x 2) of a 15 CMOS color solid-state image pickup device according to a seventh embodiment of the invention. Primary color signals of two colors can be read from all the pixels (light-receiving sections) with the complementary color filters Ye or Cy stacked thereon. Hence, two channels of read signal amplification circuits (i.e., 20 122, 124 and 126, 128) are provided.

The present embodiment requires only two types of color filters. When compared with the conventional case where three or four types of color filter are used, the number of color filters used is reduced, thereby yielding an advantage of easy 25 manufacture. Since the G signal can be obtained directly from

all the light-receiving sections, the G signal is subjected to signal processing as a luminance signal. As a result, the resolution of a photographed image can enhanced.

(Eight Embodiment)

5 Fig. 45 is a schematic surface view of a CMOS color solid-state image pickup of single plate type according to an eight embodiment of the invention. A difference between the eight embodiment and the sixth and seventh embodiments lies only in the arrangement of color filters to be stacked on the  
10 light-receiving sections. Only the magenta (Mg) filter of a complementary color system and the green (G) filter of a primary color system are used in this embodiment, and the Mg and G filters are alternately arranged in both vertical and horizontal directions.

15 The cross-sectional structure of the light-receiving section with the Mg filter stacked thereon is identical with that shown in Fig. 31B (or Fig. 40B). The potential profile of the light-receiving section is identical with that shown in Fig. 34B, and the spectrum of the light-receiving section  
20 is identical with that shown in Fig. 36B. Of the incident light, the B signal component and the R signal component are output from the light-receiving section with the Mg filter stacked thereon.

The cross-sectional structure of the light-receiving  
25 section with the Ye filter stacked thereon is identical with

that shown in Fig. 32B (or Fig. 41B). Further, the potential profile of the light-receiving section is identical with that shown in Fig. 35B, and the spectrum of the light-receiving section is identical with that shown in Fig. 37B. More

5 specifically, of the incident light, only the G signal component is output from the light-receiving section with the G filter stacked thereon. In the embodiment, a G signal component which is unaffected by the B and R light beams is obtained through use of the G filter of a primary color system.

10 Specifically, in the CMOS color solid-state image pickup device of the embodiment, the light-receiving section with the Mg filter stacked thereon is deficient of the G signal component, and the light-receiving section with the G filter stacked thereon is deficient of the B and R signal components.

15 As shown in Fig. 46, at the position of the light-receiving section with the G filter stacked thereon, color information is reproduced by use of two values. One value is determined by adding together the G signal component directly obtained by means of a first color signal reading operation and the R  
20 signal components obtained from the vertically and horizontally adjacent light-receiving sections by the first color signal reading operation and averaging the resultant sum. The other value is determined by adding up the B signal components obtained from the vertically, horizontally adjacent light-receiving sections by means of a second color signal reading operation

and averaging the resultant sum. At the position of the light-receiving section with the Mg filter stacked thereon, color information is reproduced through use of a value determined by adding together the directly-obtained B and R signal 5 components and the G signal components obtained from the vertically, horizontally adjacent light-receiving sections.

Fig. 47 is analogous to Figs. 39 and 44; that is, a two-dimensional plan view corresponding to four pixels (G x 2, Mg x 2) of a CMOS color solid-state image pickup device 10 according to an eighth embodiment of the invention. The internal configuration of the light-receiving section is identical with the light-receiving section having a corresponding color filter shown in Fig. 39.

Fig. 48 shows spectra of the CMOS color solid-state image pickup device of the embodiment. Basically, the spectra is formed by combination of the spectra shown in Fig. 36B and that shown in Fig. 37B. Characteristics substantially identical with the spectral characteristics of the related-art image sensor using only the primary color filters; that is, faithful 20 color reproduction, can be implemented.

(Ninth Embodiment)

Fig. 49 is a schematic surface view of a CMOS color solid-state image pickup of single plate type according to a ninth embodiment of the invention. A difference between the 25 ninth embodiment and the sixth, seventh, and eighth embodiments

lies only in the arrangement of color filters stacked on the light-receiving sections. In the embodiment, the light-receiving sections with the magenta (Mg) filter of a complementary color system stacked thereon and the

5 light-receiving sections with a mere transparent planarized film [hereinafter also called "white filter" (W)] and without use of a color filter are alternately arranged in both the vertical and horizontal directions.

The cross section of the light-receiving section with  
10 the Mg filter stacked thereon is identical with that shown in Fig. 31B (or Fig. 40B). The potential profile of the light-receiving section is identical with that shown in Fig. 34B, and the spectrum of the light-receiving section is identical with that shown in Fig. 36B. Of the incident light, the B signal  
15 component and the R signal component are output from the light-receiving section with the Mg filter stacked thereon.

A signal including all the B, G, and R signals of the incident light; that is, the luminance signal (Y), is output from the light-receiving sections that do not use any color  
20 filters.

In the CMOS color solid-state image pickup device of the embodiment, the light-receiving section with the Mg filter stacked thereon is deficient of the G signal component, and the light-receiving section with the white filter (transparent planarized film) stacked thereon produces only a luminance  
25

signal.

As shown in Fig. 50, at the position of the light-receiving section with the Mg filter stacked thereon, color information is reproduced as follows. Namely, the R signal component 5 directly obtained by means of the first signal reading operation, the B signal component directly obtained by means of the second signal reading operation, and the luminance signal (B+G+R) obtained from the vertically, horizontally-adjacent light-receiving sections by the first signal reading operation, 10 and averaging the resultant sum. The directly-obtained R and B signal components are then subtracted from the average, thereby producing a G signal component.

The B signal components obtained from the vertically, horizontally adjacent light-receiving sections are added 15 together, and the resultant sum is then averaged. Further, the R signal components obtained from the vertically, horizontally adjacent light-receiving sections are added together, and the resultant sum is then averaged. The thus-determined mean B and R signal components are subtracted 20 from the directly-obtained luminance signal, thereby preparing a G signal component. At the position of the light-receiving section with the white filter stacked thereon, color information is reproduced through use of the G signal component.

Fig. 51 is a cross-sectional schematic view taken along 25 line LI-LI shown in Fig. 49. Fig. 52 is a cross-sectional view

showing that the microlens, the light-shielding film, and the transparent planarized film are stacked one on top of the other. Those elements which are the same as those of the sixth embodiment are assigned the same reference numerals, and hence their 5 repeated explanations are omitted.

The  $N^+$  layer (n3') 156 (color signal detecting layer) for storing signal electric charges corresponding to the amounts of all incident light beams, that is, the R, G, and B light beams, having passed through the transparent planarized film 10 (W) 155 is formed in the surface of the P well 115 provided at a surface portion of the semiconductor substrate 110 to a depth of 0.5 to 1.5  $\mu\text{m}$ .

Fig. 53 is a view showing a potential profile of the light-receiving section having no color filters. The electric 15 charges produced by the red light that has penetrated to a position deeper than the  $N^+$  layer (n3') 156 fall into a well along the potential profile. Hence, even when the depth of the  $N^+$  layer (n3') 156 is set to a shallow position on the order of 0.5  $\mu\text{m}$ , a luminance signal including the R signal component 20 cannot be obtained. However, the depth of the  $N^+$  layer (n3') 156 is preferably set such that spectral sensitivity close to human visual sensitivity is achieved in the respective R, G, and B wavelengths.

Fig. 54 is a view showing spectral sensitivity spectra 25 of the CMOS color solid-state image pickup device of the

embodiment. The B and R signals having passed through the magenta filter Mg are separated from each other without involvement of an overlap. The signal (W) of the light (B+G+R) having passed through the white filter has spectra whose peak 5 appears at the wavelength of the G signal (in the vicinity of 540 nm) including all visible light wavelengths.

In the present embodiment, particularly the light-receiving section corresponding to white (W) can utilize wavelength components of all visible ranges. Hence, there is 10 no substantial loss of the incident light component. When compared with the case where complementary color filters are stacked on all the light-receiving sections as in the case of the first embodiment, an attempt can be made to enhance 15 sensitivity to a much greater extent. Moreover, there is also a characteristic of the ability to directly produce a high-sensitivity luminance signal (R+G+B). In addition, since only the Mg filter is used as a color filter, the process for laminating the color filter becomes easy.

The foregoing embodiments have been described by means 20 of taking the CMOS color solid-state image pickup device as an example of the MOS color solid-state image pickup device. However, the present invention can also be applied to other types of color solid-state image pickup device, such as NMOS and PMOS color solid-state image pickup devices.

25 The present invention can yield the following advantages:

(1) Since color signal components of two colors can be independently detected from one light-receiving section (pixel), incident light can be effectively converted into an electric signal, and hence enhancement of sensitivity becomes

5 possible.

(2) Since primary color signals can be taken directly out of a solid-state image pickup device using complementary color filters, and hence faithful color reproduction becomes feasible.

10 (3) Since color filters of a complementary color system are used along with utilization of spectral characteristics of the light-receiving sections in the depthwise direction of the substrate, the amount of an overlap existing between spectra (R, G, and B) becomes smaller. As a result, faithful color

15 reproduction becomes feasible.